EMPro 2012
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Examples

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The following third-party libraries are used by the NlogN Momentum solver:

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Intel@ Math Kernel Library, http://www.intel.com/software/products/mkl

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Antenna

This section provides information about the following topics:

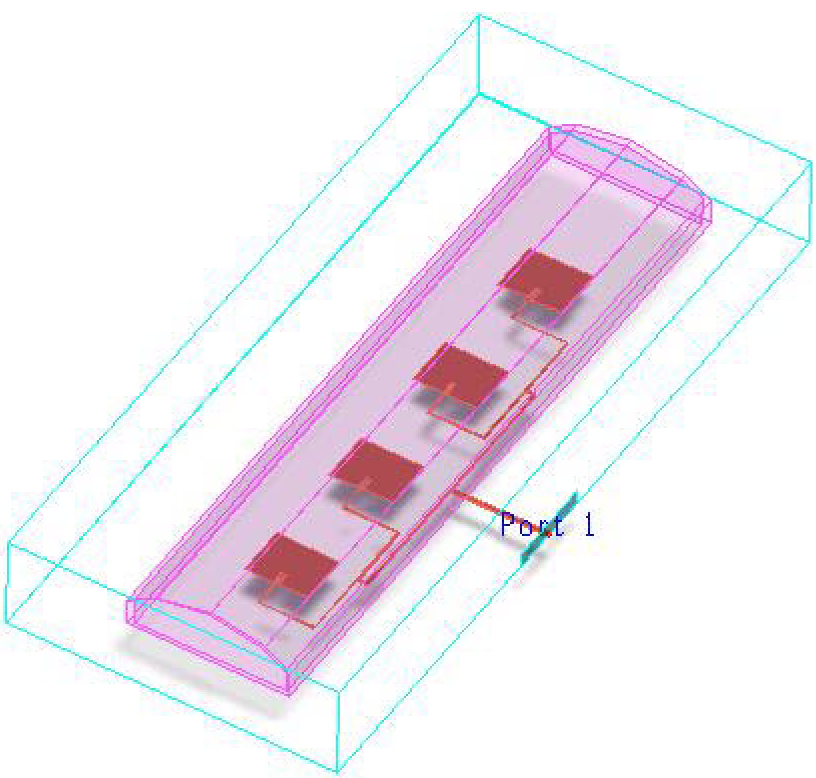
- *Antenna With Radome* (example)
- *Microstrip Dipole Antenna* (example)
- *Microstrip Patch Antenna* (example)
- *Patch Antenna with TNC Connector* (example)

Antenna With Radome

Location: In EMPro, choose **Help > Examples > Antenna With Radome** to open the project.

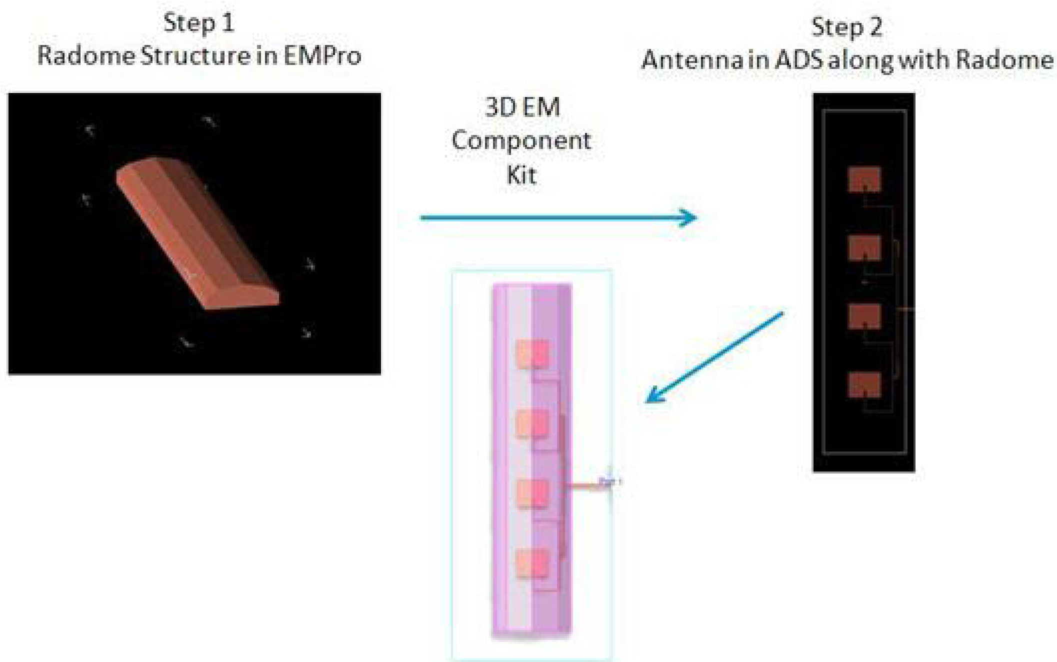
Objective

This example describes the application of EMPro and ADS integration. EMPro provides a strong linkage to ADS. Any 3D geometry or EMPro solved project can be exported to ADS in the form of design kits for further analysis. In this example, a radome is generated in EMPro and integrated to planar antenna in the ADS environment. Radome is used as a protective shield to Antenna structure and placed around the antenna geometry. The presence of Radome affects the antenna S parameter and radiation pattern. The radome affect analysis is normally avoided because modeling 3D geometries of radome is difficult. However, EMPro provides easy to use modeling tools facilitating modeling of any complicated 3D structures. The robust CAD import feature of EMPro also provides an alternative where any complicated radome structure can be imported to EMPro and further project or kit can be build and exported to ADS. Planar antennas that are designed in ADS environment can be analyzed in presence of radome by importing radome structure from EMPro and carrying out complete analysis in ADS environment using FEM simulator. The planar microstrip antenna used for this analysis is shown in the following figure within a radome structure. This antenna is operating at C band.



Setup

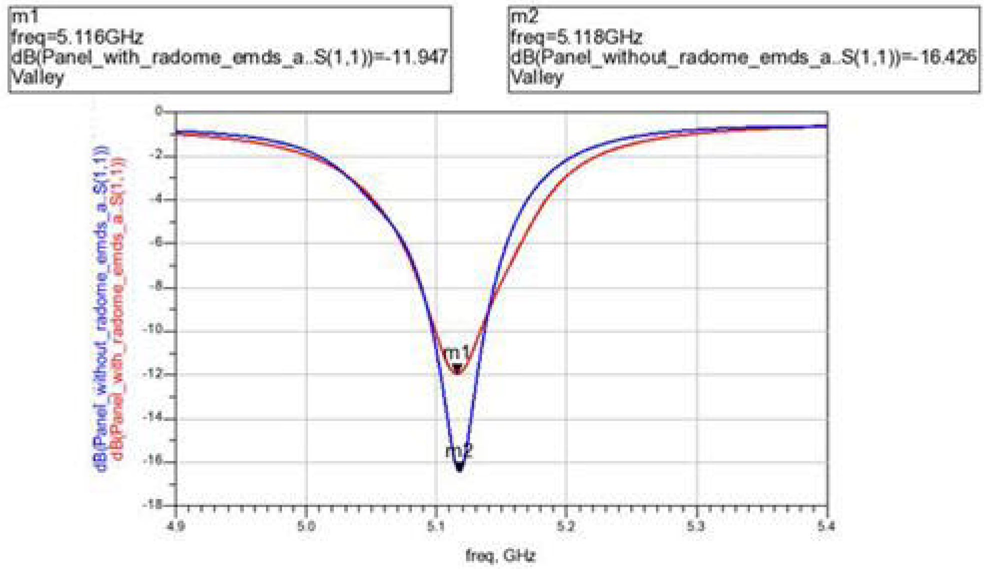
The radome structure is designed in EMPro and brought as a design kit into ADS. The analysis of the complete structure is performed in ADS by using the FEM simulator. Semicircular radome structure along with its stand is generated in EMPro using geometry modeling tools. The 3D EM Component design kit is generated using ADS link tab of EMPro. This kit is installed in ADS by following the installation process of the design kit. Next, the footprint of radome is positioned over the microstrip patch antenna array. The radome is placed at 10mm distance from antenna surface. The complete geometry is then subjected to FEM simulation for calculating the S parameter and radiation pattern. The following figure illustrates the design flow:



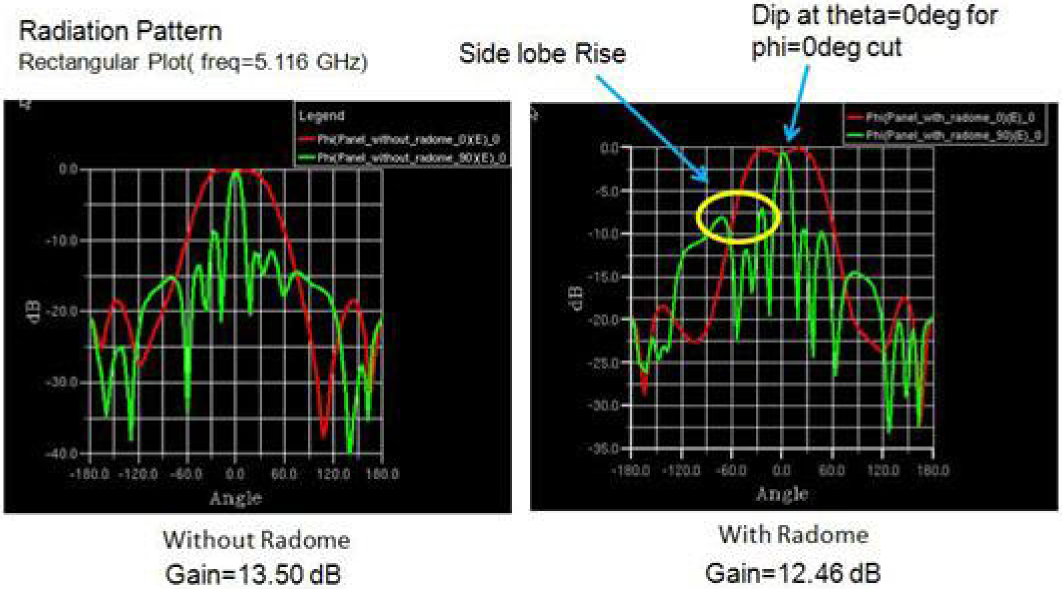
Use the following archive file:
Archive file: **Radome.zep**

Analysis

The S parameter of antenna with and without radome is shown in the following figure. The S parameter changes in presence of radome.



The 2D radiation pattern with and without radome is shown in Figure 4 in phi angle cut plane of 0 degree. The antenna radiation pattern with radome shows increase in side lobe level and a small dip at the peak of main beam. The gain value of the antenna is also reduced in presence of radome.



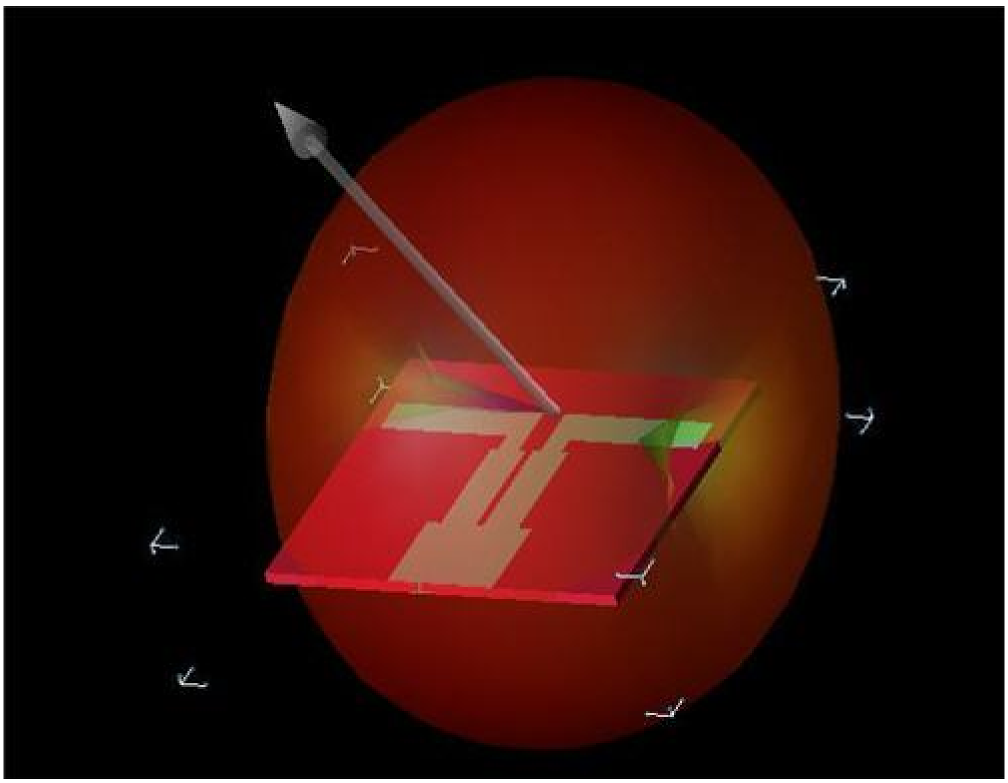
> **Note:**
> You need to install the Radome Kit in ADS to perform the analysis. Within this project, **EMProRadome_DesignKit.zip** and ADS project **Antenna_with_radome.zip** are also placed.

Microstrip Dipole Antenna

Location: In EMPro, choose **Help > Examples > Microstrip Dipole Antenna** to open the project.

Objective

This example describes the design of a Microstrip Dipole Antenna using both FDTD ad FEM simulations in EMPro. The Microstrip Dipole Antenna is designed by Orban Microwave Products, Leuven, Belgium. This antenna in planar microstrip configuration is designed on FR4 substrate of thickness 1.6 mm. The dipole antenna is fed through a via from 50ohm microstrip line. The geometry modeling tools of EMPro are used to model two dimensional planar dipole and three dimensional via structure. The far field sensor is used to get far field radiation pattern in 2D and 3D. The antenna geometry is shown in the following figure:



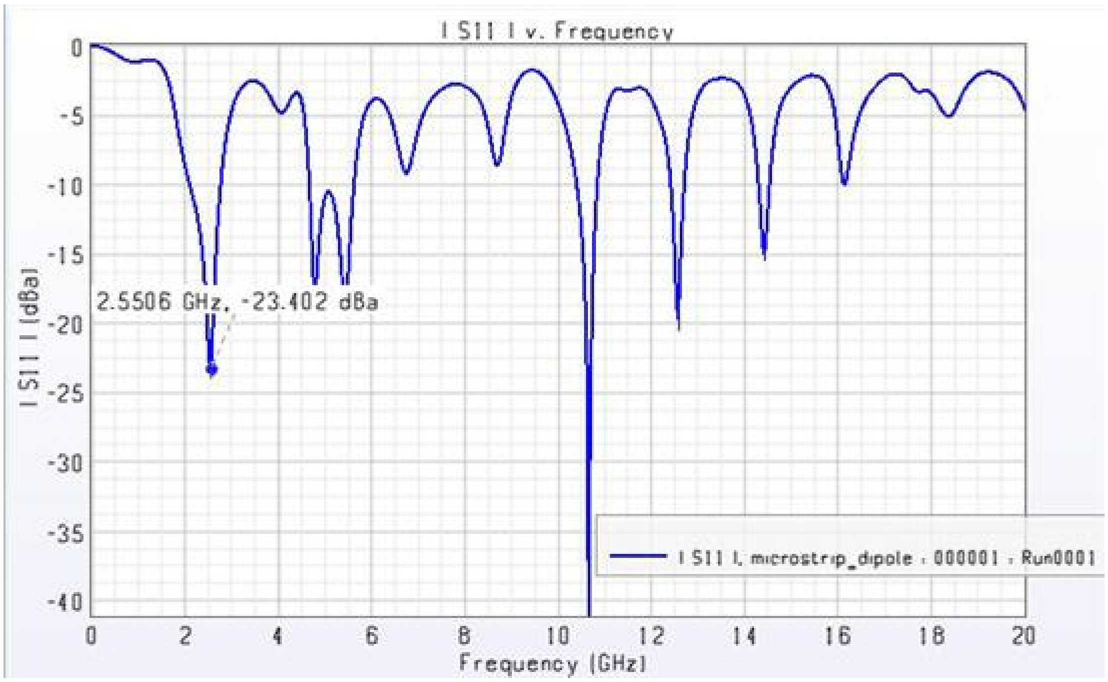
Setup

FDTD:
The Broadband Gaussian Waveform is used to activate the source to achieve a broadband response for the antenna. The base cell size of 1mm is used to mesh the structure. It does not generate sufficient mesh along the Z direction, where the thickness of the substrate exists. To achieve accuracy, at least 3 cells should exist along the thickness of the substrate. To accommodate this, an adaptive mesh of 0.4mm is used in the Z direction within the thickness of the substrate. In addition, for all the objects of the geometry, automatic fixed points is used for gridding properties. This ensures that the meshes are falling on the edges of the objects. The generated mesh provides results up to 30GHz in a single simulation.

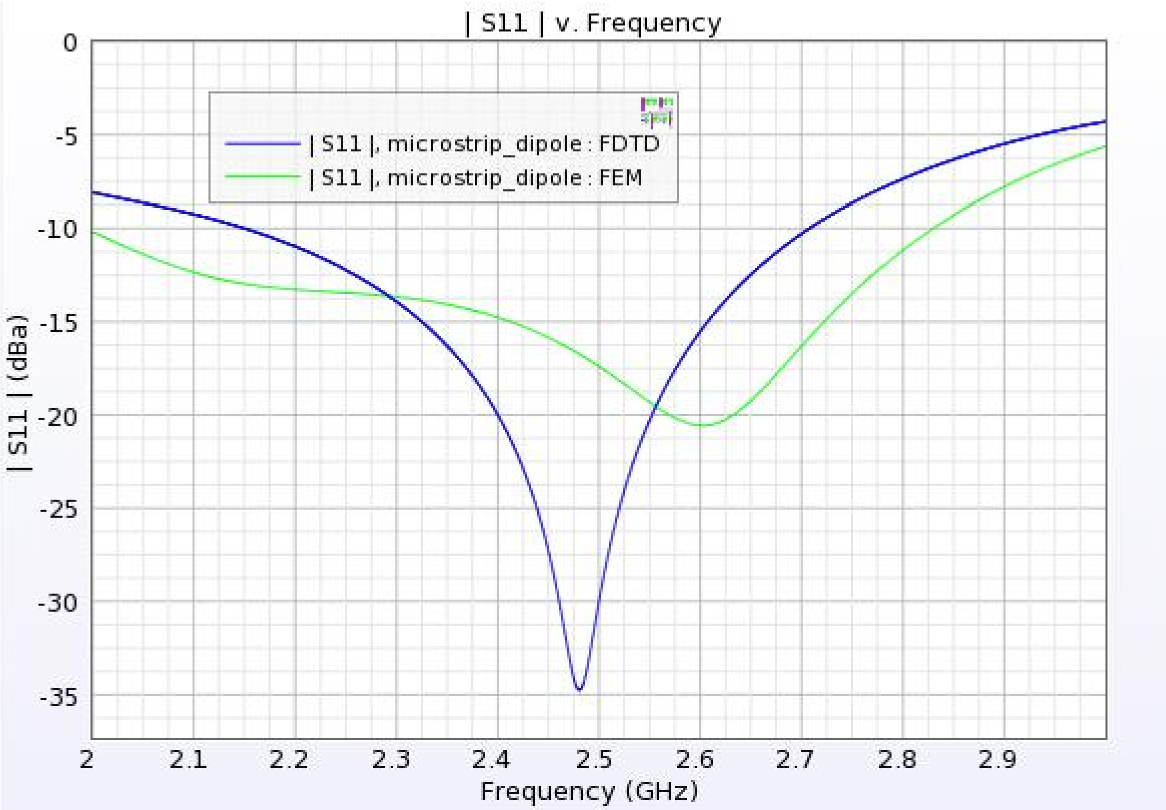
FEM:
For FEM simulation same geometry, port and boundary setup as of FDTD is used. FEM padding of 60 mm is used in all the directions.
Use the following archive file:
Archive file: **microstrip_dipole.zep**

Analysis

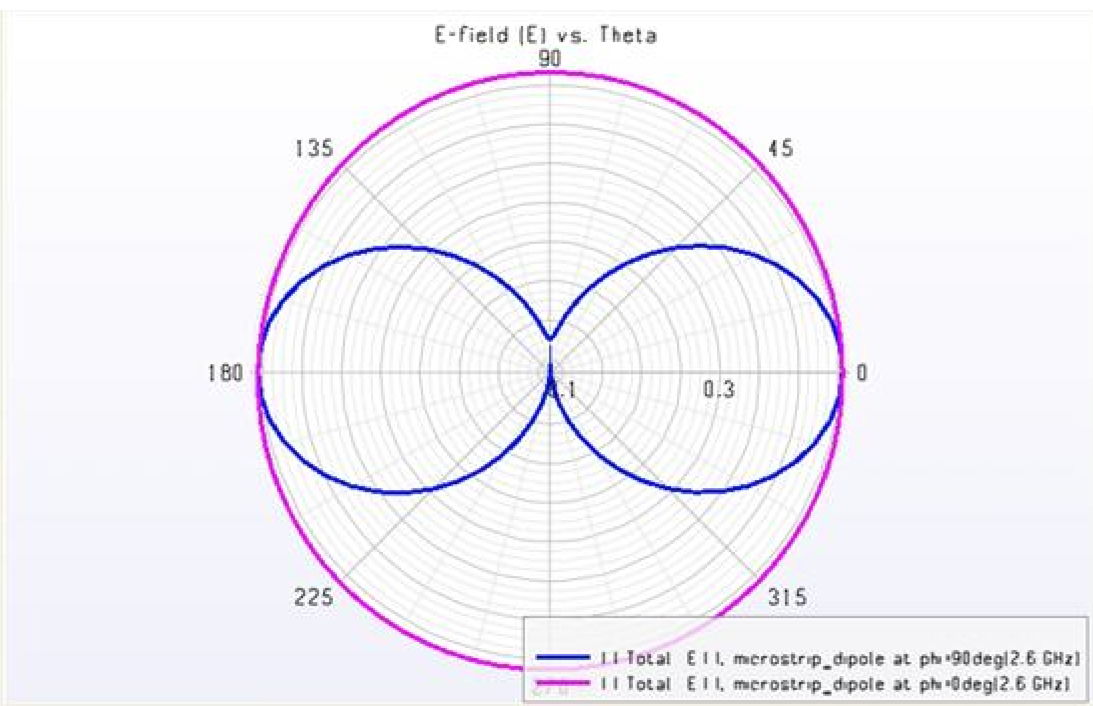
The return loss (S11) for the antenna is shown in the following figure:



Comparison of S parameter between FDTD and FEM is shown in following figure:



The radiation pattern of Microstrip Dipole Antenna in Phi at 0 degree and Phi at 90 degree cut planes in polar plot for 2.6 GHz from FDTD simulation is shown in the following figure. The pattern is omni-directional (doublet) and is circular in phi at degree plane. In phi at 90 degree, the pattern lobes are not circular. They are flattened and the radiation intensity is greater than 0dB.The patterns from FEM are similar to FDTD.

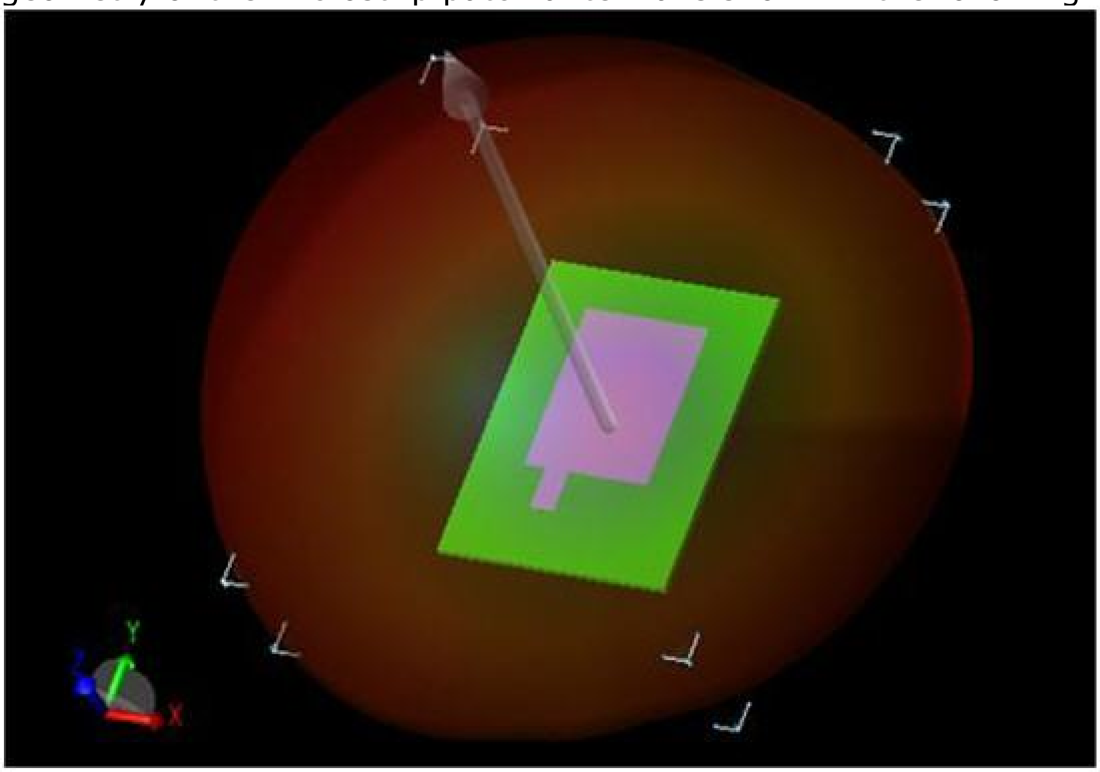


Microstrip Patch Antenna

Location: In EMPro, choose **Help > Examples > Microstrip Patch Antenna** or **Help > Examples > Microstrip Patch Antenna with parameters** to open the projects.

Objective

These examples illustrates the design of Microstrip patch antenna using both FDTD and FEM simulations. This example is based on the paper "Applications of the Three Dimensional Finite Difference Time Domain Method to the Analysis of Planar Microstrip Circuits " by Sheen et al in the July 1990 issue of IEEE Transactions on Microwave Theory and Techniques. In this issue of MTT, you can refer to page numbers from 849 to 856 for more information. In this example, the Surface sensor that is located at port 1 is used to evaluate E,H,B field quantities along with Surface current Jc and poynting vector S. The far field sensor is used to get far field radiation pattern in 2D cut planes and 3D. The geometry of the microstrip patch antenna is shown in the following figure:



Setup

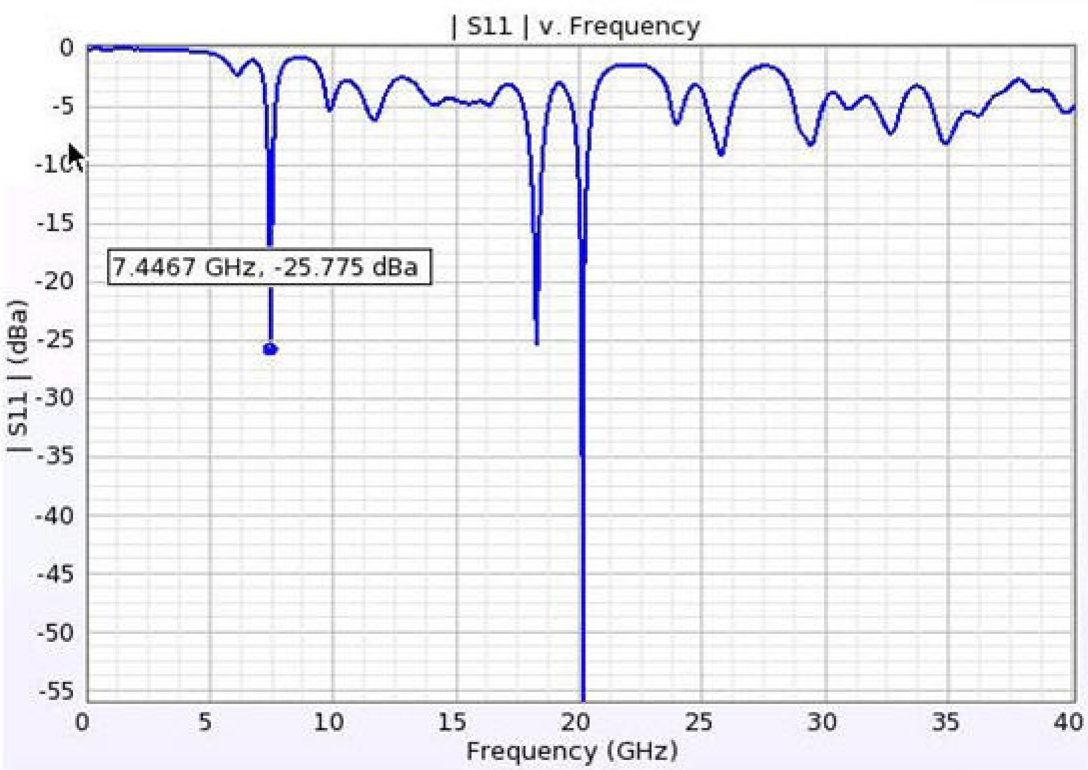
FDTD:
A Gaussian pulse is used as the source waveform for wideband frequency response. The base cell size of 0.3 mm is used for mesh in x and y directions. The base cell size 0.1mm is used along the thickness of the substrate. In addition, for all the objects of the geometry automatic fixed points is used in gridding properties. This ensures that meshes are falling on the edges of the objects. The absorbing boundary condition is used in all the sides with finite ground plane on the back of the substrate.

FEM:
For FEM simulation same geometry, port and boundary setup as of FDTD is used. FEM

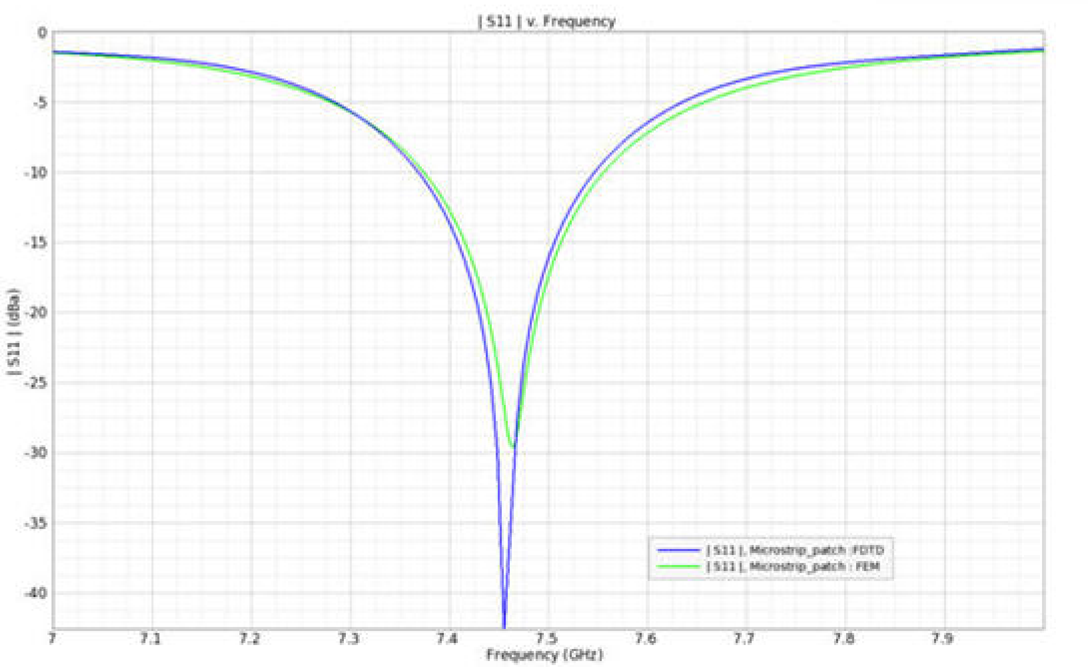
padding of 20 mm is used in all the directions.
Use the following archive files:
Archive files: **Microstrip_patch.zep and Microstrip_patch_par.zep**

Analysis

Microstrip_patch.ep is the initial patch with fixed input stub length. The Gaussian waveform is used with the steady state data collected at 7.23GHz, 17.68GHz, 19.45GHz, 24.7GHz and 28.61GHz. The S parameter results over the band and at discreet frequency points are calculated. The S parameter plot over the frequency band is shown in the following figure:



Comparing S Parameter Plot for FDTD and FEM

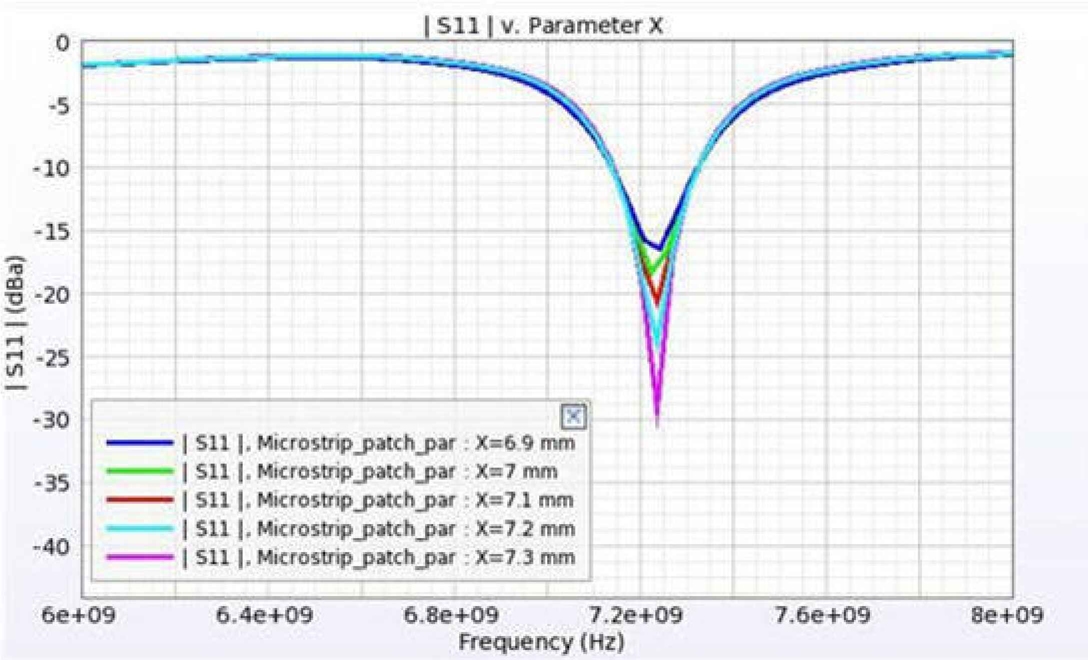


There is close matching between S parameter result obtained from FEM and FDTD. These results also match closely with paper reported results.

The radiation plots between FDTD and FEM are close. The Gain figure at discreet frequency points are also very close. For example at 7.47 GHz (where S parameter are almost same from both FEM and FDTD) the Gain from FDTD is 7.99 dBi & from FEM is 8 dBi.

In addition, the E,H,B fields as well as the surface current J with time steps are visible from the Near field sensor for FDTD. For FEM E and H plots can be seen from Advanced Visualization.
In Microstrip_patch_par.ep, the input stub length is specified as a parameter(X). The value of this parameter is varied from 6.9 mm to 7.3 mm in the steps 0.1 mm to vary the length of the stub.

The following figure displays the result of varying length on the S parameter.



Note:
Simulate the project Microstrip_patch.ep to see the results. The FDTD S parameter result for Microstrip_patch_par.ep vary slightly from Microstrip_patch.zep, this is because of different gridding used in Microstrip_patch_par.ep. For more information about how to create a Microstrip patch antenna design, see *Microstrip Patch Antenna* (fdtd).

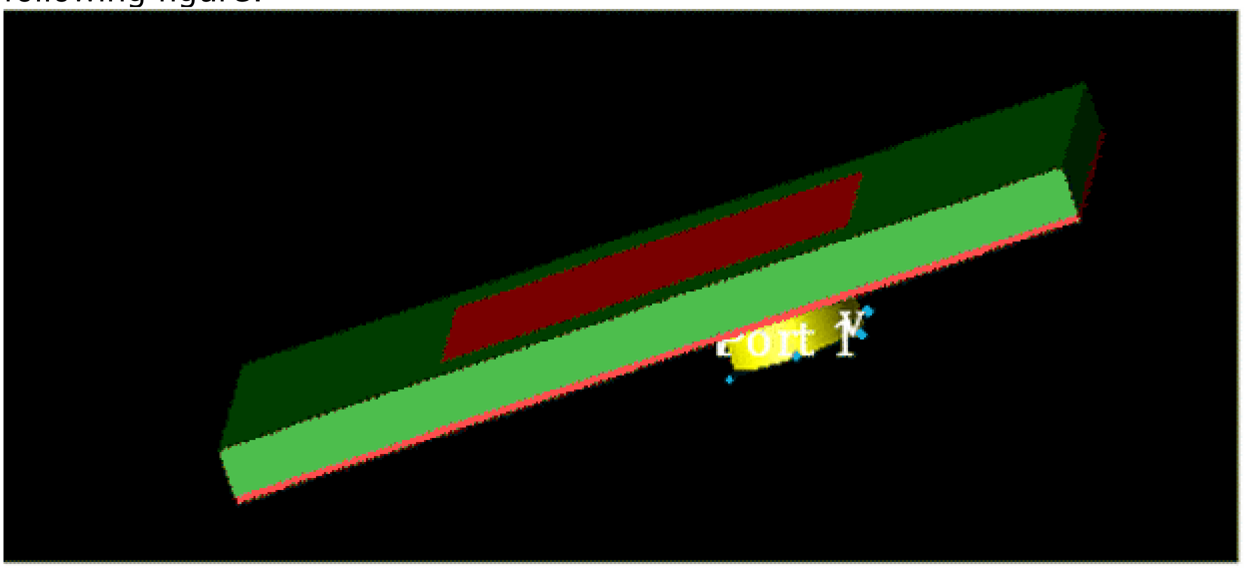
Patch Antenna with TNC Connector

Location: In EMPro, choose **Help > Examples > Patch Antenna with TNC**

Objective

This example illustrates the application of EMPro in designing a microstrip patch antenna with a TNC connector using FEM simulator. The TNC connector feeds the antenna from back-side of the antenna. The design band is C band. The patch antenna is designed on a substrate of 2.47 dielectric constant having thickness of 3.2 mm. The far field sensor is used to get far field radiation pattern in 2D cut planes and 3D.

The geometry of the microstrip patch antenna with TNC connector is shown in the following figure:



Setup

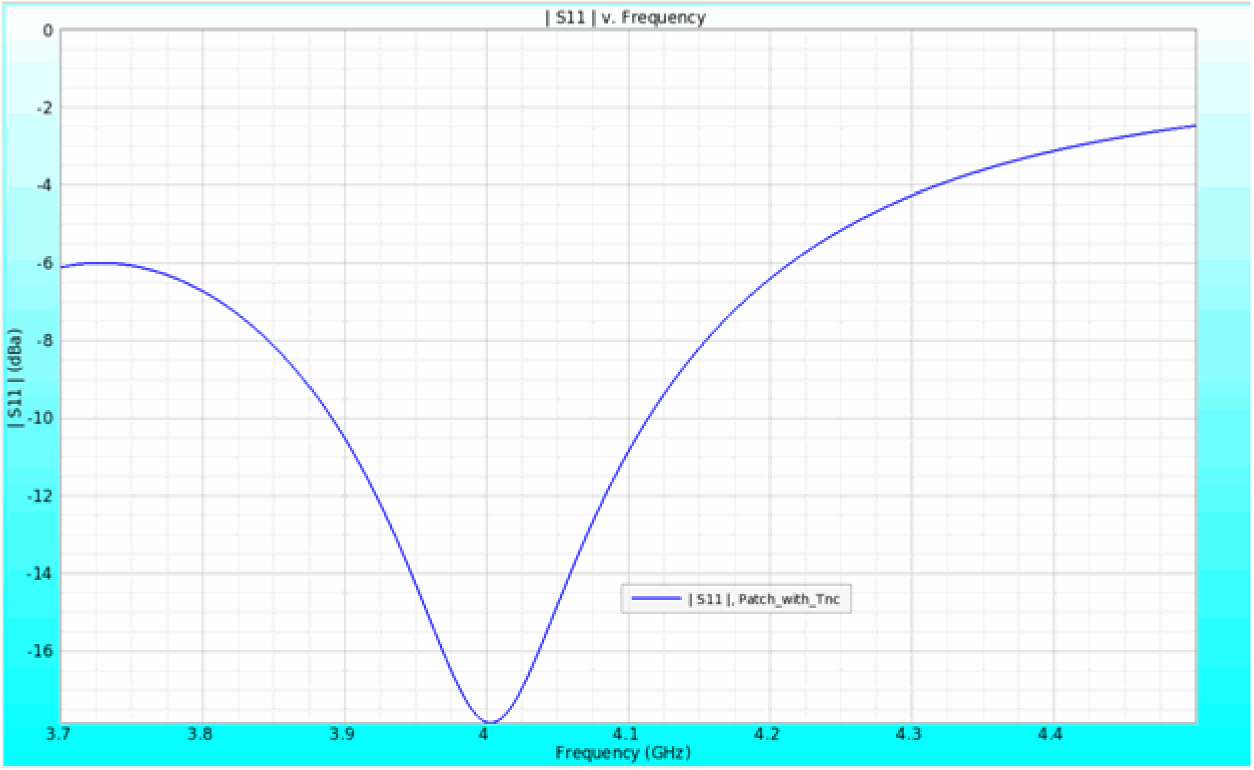
FEM:
FEM padding of 20 mm in upper Z, 0 mm in lower z and 30 mm in x and y directions are used. Absorbing boundary condition is used in all the directions.
Waveguide port is used at the input of TNC connector.

Use the following archive files:
Archive files: **Patch_with_TNC.zep**

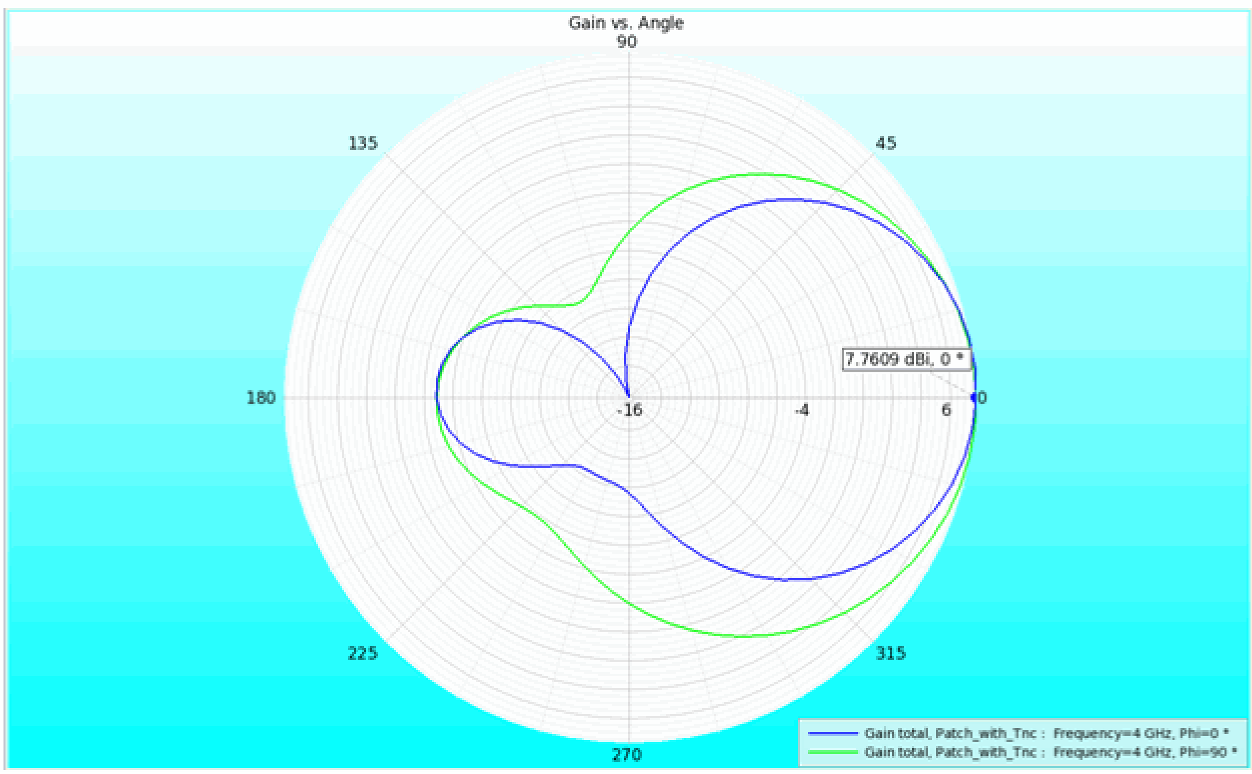
Analysis

The frequency sweep is used from 3.7 GHz to 4.5 GHz. The FEM mesh refinement is carried out at the highest frequency of range.
The S parameter plot over the frequency band is shown in the following figure:

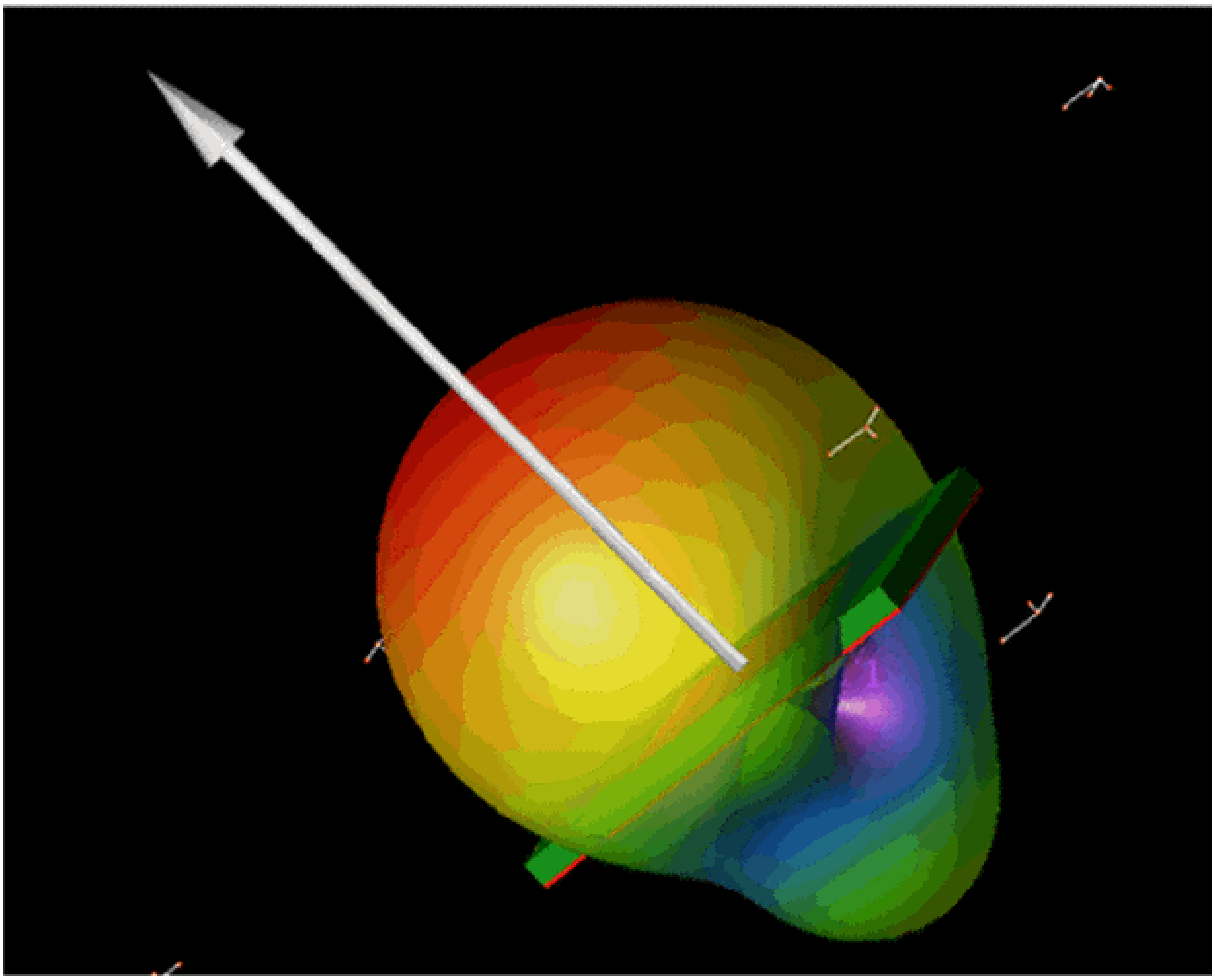
S Parameter Plot



The resonance frequency of the antenna is 4 GHz.
The 2D gain pattern in Phi=0deg and 90 deg cut plane is shown below:



The 3D gain pattern is also shown in following figure:



Note
In **FEM Simulation > Frequency Plans > Field Storage > User Defined Frequency** is used. So the field data and radiation data is available at 3.7,4 and 4.5 GHz. If field and radiation data is required at any other frequency,then re-simulate the project using reuse option in FEM simulation.

Waveguide and Component

This section provides information about the following topics:

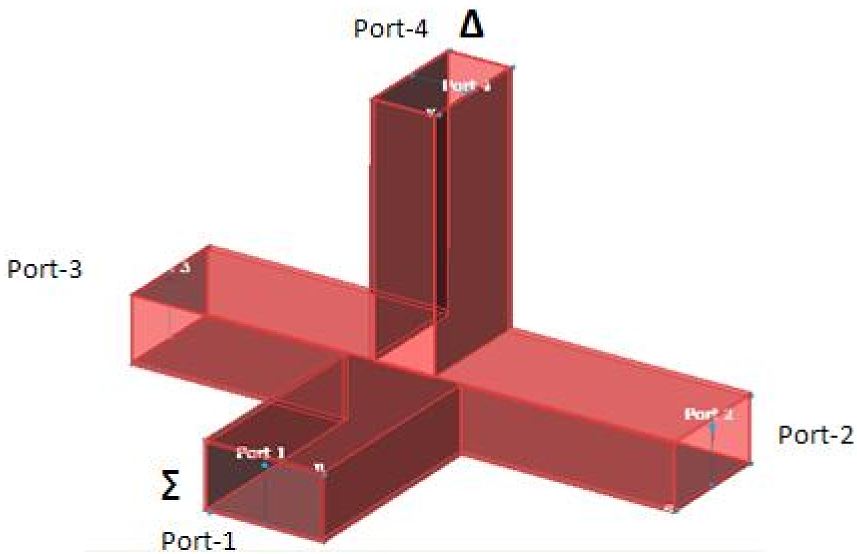
- *Magic Tee* (example)
- *Waveguide Power Divider* (example)
- *Waveguide Power Divider with Symmetric Plane* (example)
- *Waveguide to Coaxial Line Transition* (example)

Magic Tee

Location: In EMPro, choose **Help > Examples > Magic Tee** to open the project.

Objective

This example shows the application of waveguide ports in EMPro. A magic tee is a four-port, 180 degree hybrid splitter, realized in waveguide. Like all of the coupler and splitter structures, the magic tee can be used as a power combiner, or a divider. It is ideally lossless, so that all power into one port can be assumed to exit the remaining ports. Port 1 is the (sum) port, and is called the H-plane port. A signal incident on port 1 equally splits between ports 2 and 3, and the resulting signals are in phase. Ports 2 and 3 are called the co-linear ports, because they are the only two that are in line with each other. Port 4 is the (difference or delta) port, and is called the E-plane port. A signal incident on the difference port splits equally between ports 2 and 3, but the resulting signals are 180 degrees out of phase.



This example also helps to visualize how the E-field of a signal entering the sum port remains in the same up-and-down direction and polarity as it splits to ports 2 and 3, while the E-field of a signal entering the delta port wraps around in two opposing polarities as it splits between ports 2 and 3. The interior dimensions of the waveguide are 4 inch by 2 inch.

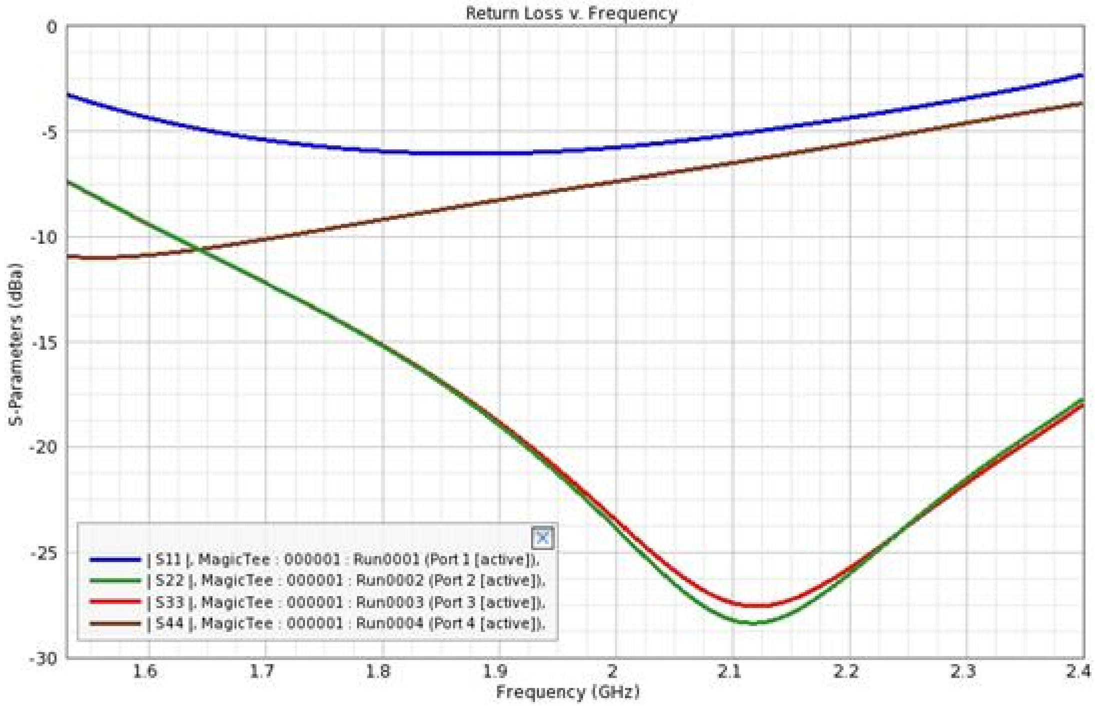
Setup

Magic Tee has been simulated with four waveguide ports each having one mode. Hollow waveguide has been modeled using shell operation. Waveguide walls are 0.1 inch thick metallic wall and it is filled with air. Simulation frequency range in from 1.4 GHz to 2.4 GHz.

Archive file: **MagicTee.zep**

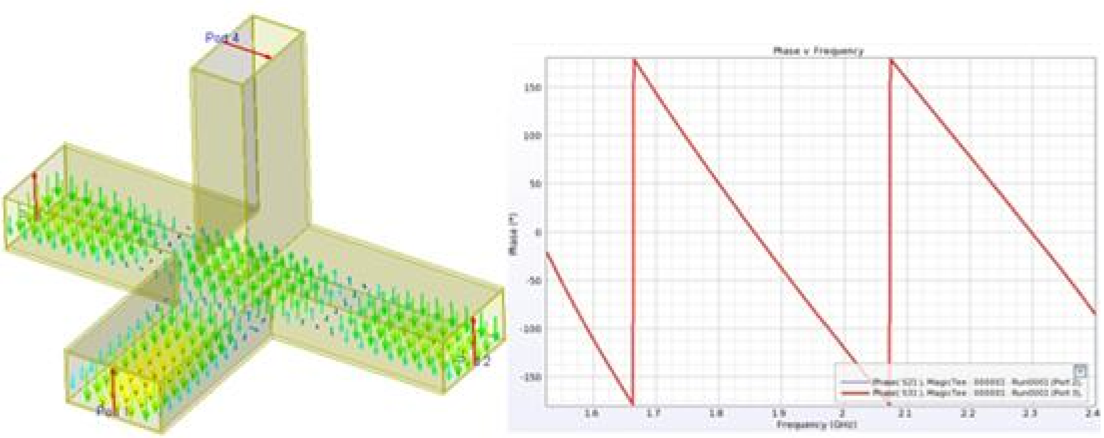
Analysis

The return loss performance of Magic Tee is shown in the following figure:



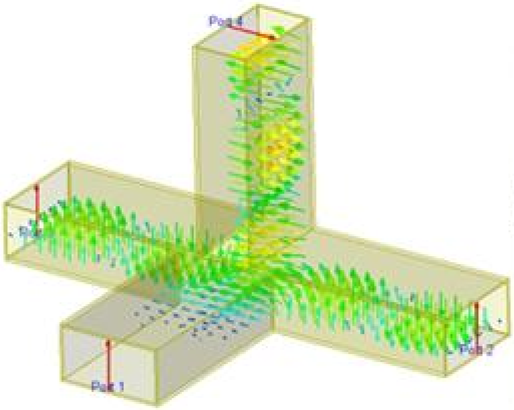
E Field and Phase Plot of Sum and Delta Ports

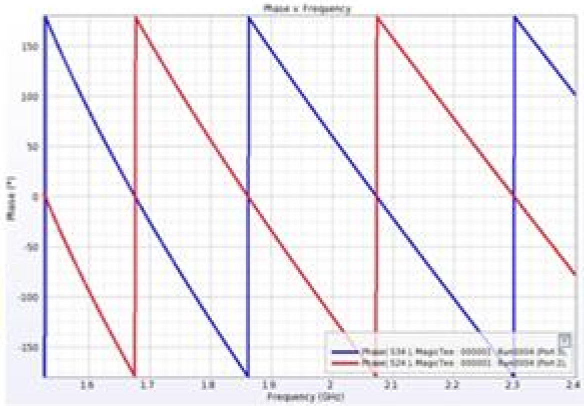
The following figure displays the E-field vectors for signals entering the sum port and diving in two collinear ports:



In this figure, the sum port excites in same phases in the collinear arms.

The following figure displays the E-field vectors for signals entering the delta port and diving in two collinear ports:





In this figure, the delta port excites in opposite phases in the collinear arms.

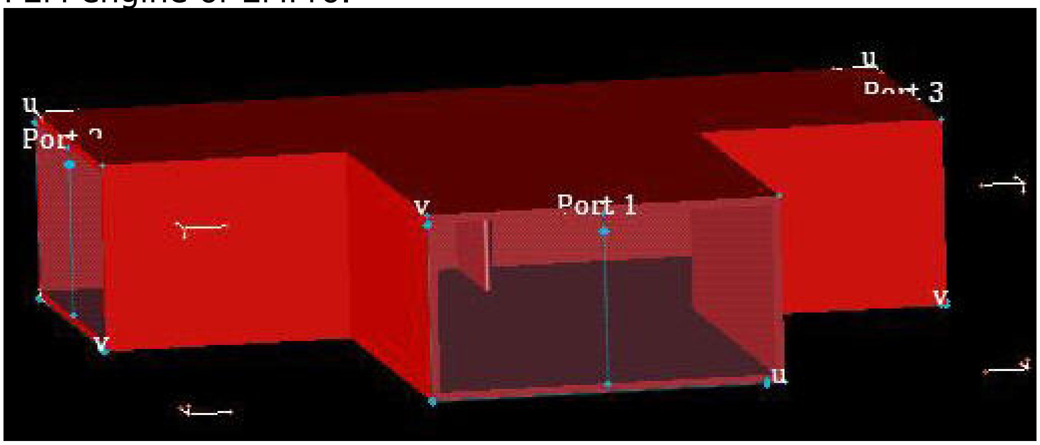
> **Note**
> Simulate the project MagicTee.ep to see the field plots in Advanced visualization results.

Waveguide Power Divider

Location: In EMPro, choose **Help** > **Examples** > **Waveguide Power Divider**

Objective

This example describes the design of waveguide power divider with waveguide ports using FEM engine of EMPro.



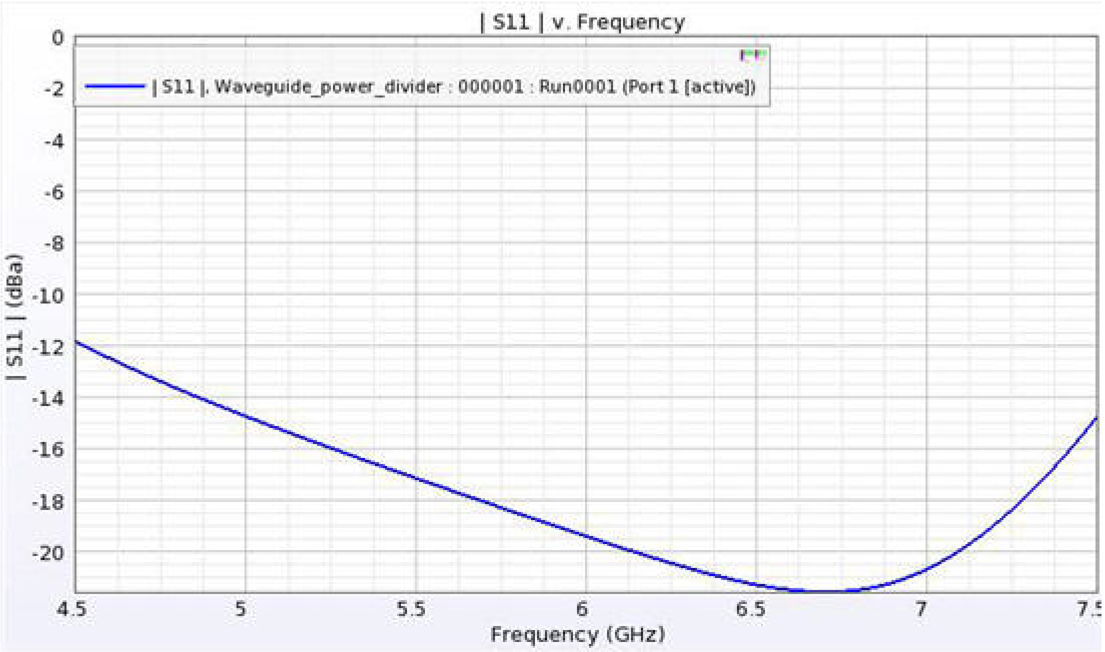
Setup

The waveguide used in power divider is WR159. This is equal power divider with input arm power divided into two output arm each having equal -3dB power. The design band is C band and a matching section is used to get return loss(S11) better than -10 dB between 4.5 Ghz and 7.5 GHz.
Archive files: **Waveguide_power_divider.zep**

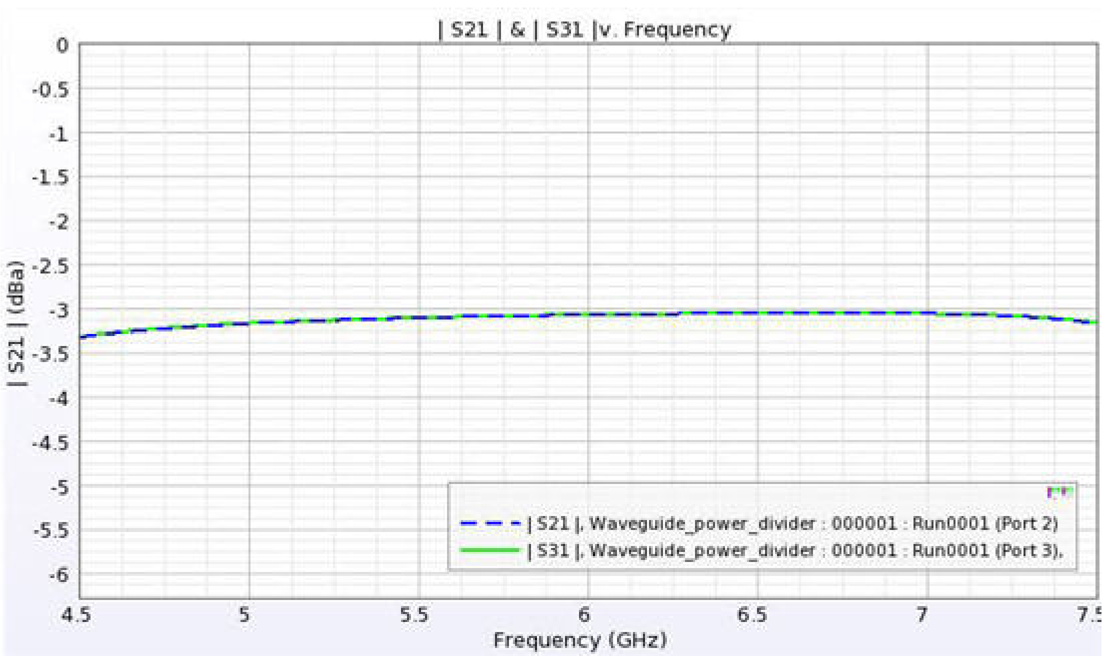
Analysis

The waveguide power divider is analyzed for dominant mode(TE01) propagation. The S parameter plot over the frequency band is shown in the following figure:

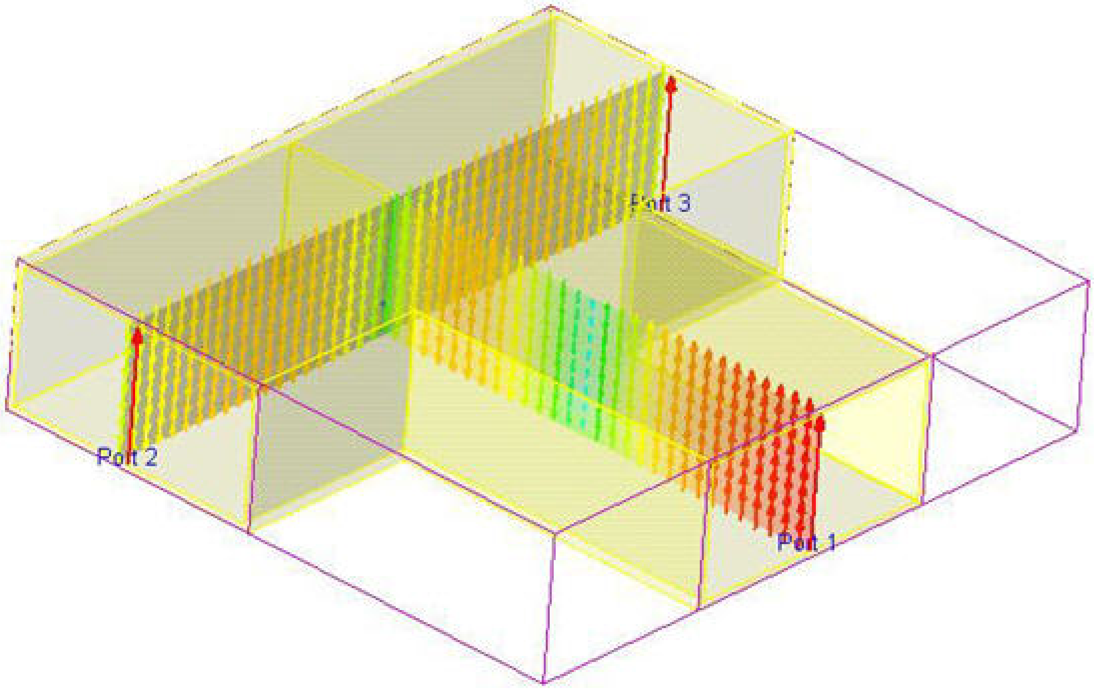
S11 Parameter Plot



S21 & S31 Parameter Plot



The field plot can be seen from Advanced visualization. Field plot for one cut plane in input and output section is shown below:



> **Note:**
> Simulate the project **Waveguide_power_divider.ep** to see the field plots in Advanced visualization results.

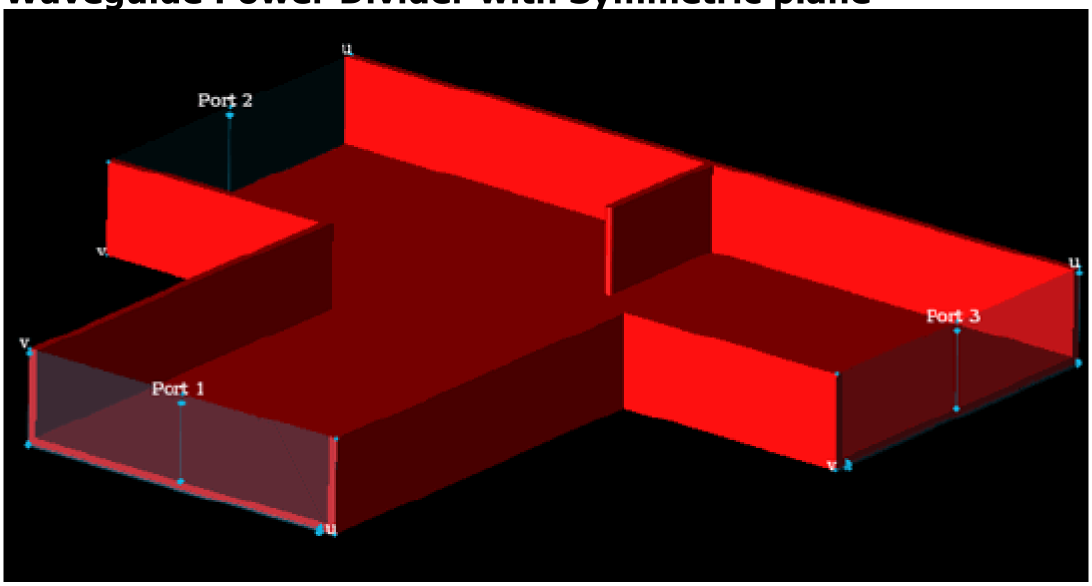
Waveguide Power Divider with Symmetric Plane

Location: In EMPro, choose **Help > Examples > Waveguide Power Divider Using Symmetry**.

Objective

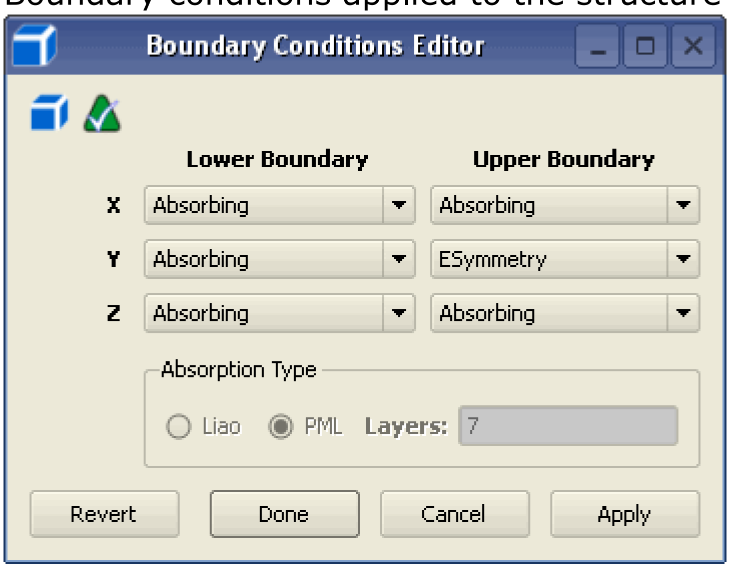
This example illustrates the application of Symmetric Plane in EMPro in designing a waveguide power divider using FEM simulator. This is same as waveguide power divider example (**Help > Examples > Waveguide Power Divider**) where half of the section is in Y direction is removed and a E Symmetric Plane Boundary Condition is applied. Since physical size is reduced to half, the memory requirement reduces giving same result.

Waveguide Power Divider with Symmetric plane



Setup

FEM:
Boundary conditions applied to the structure are as shown in the following figure:

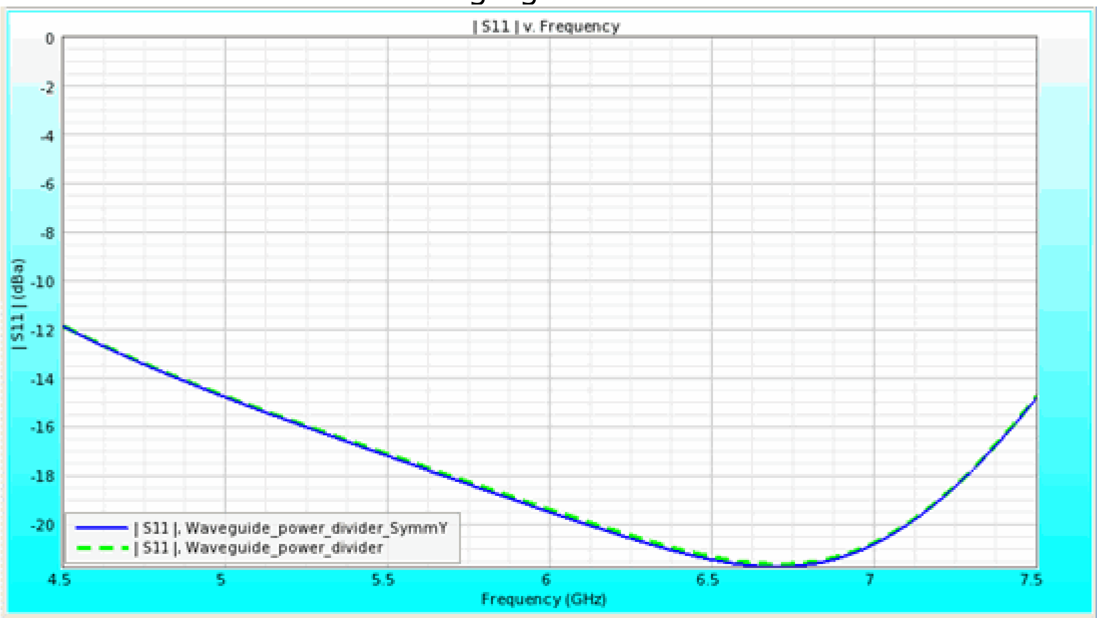


The structure in symmetric in Y direction. E Symmetric plane is applies in Upper Y. FEM padding of 0 mm is used in all the directions. Waveguide port with 1 W modal power feed is used for three ports.

Use the following archive files:
Archive files: **Waveguide_power_divider_SymmY.zep**

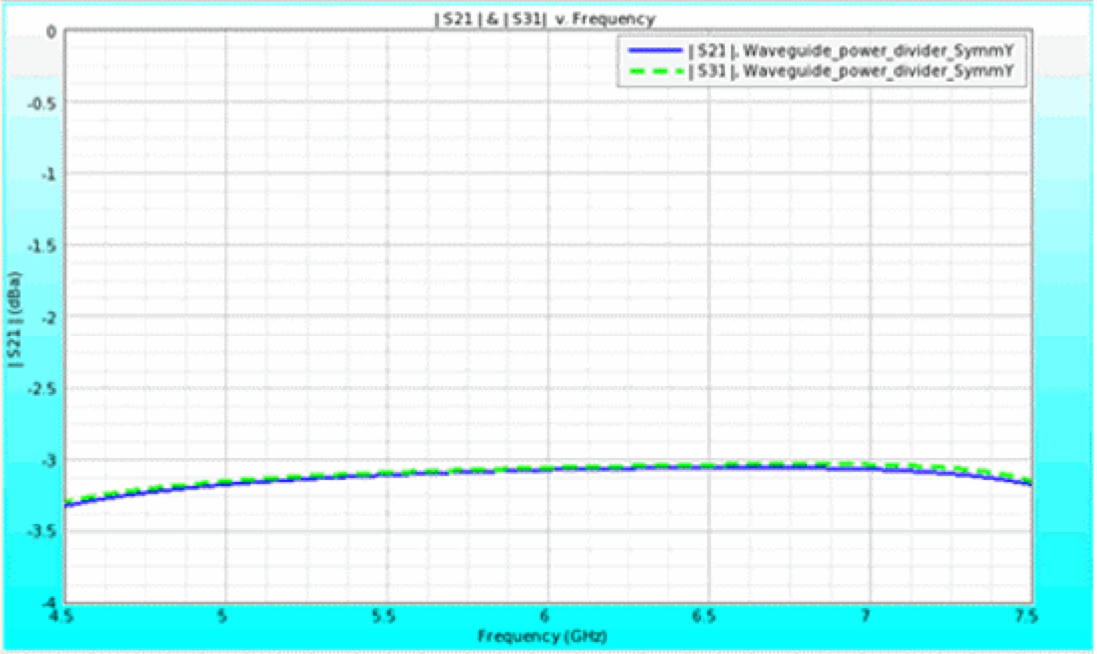
Analysis

The frequency sweep is carried out from 4 GHz to 8 GHz. The FEM mesh refinement is carried out at the highest frequency of range. The S11 parameter plot over the frequency band is shown in the following figure:



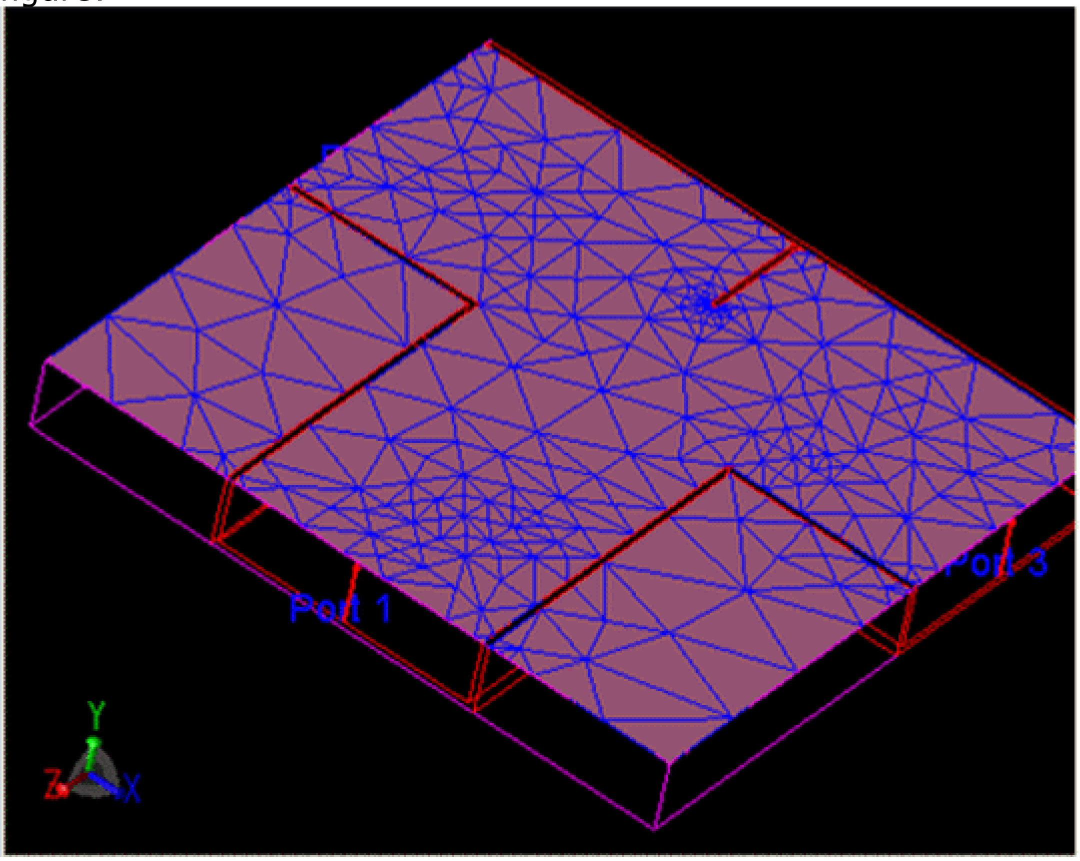
The S11 plot(blue color) is compared with S11 plot of Original Waveguide power divider and there is exact match. Hence using symmetric plane boundary condition, the physical size and hence memory requirement can be reduced achieving same S parameter result.

The S21 and S31 plot is shown in the following figure:



Symmetric Plane in Advance Visualization

The Symmetric plane can be seen in advance Visualization as shown in the following figure:

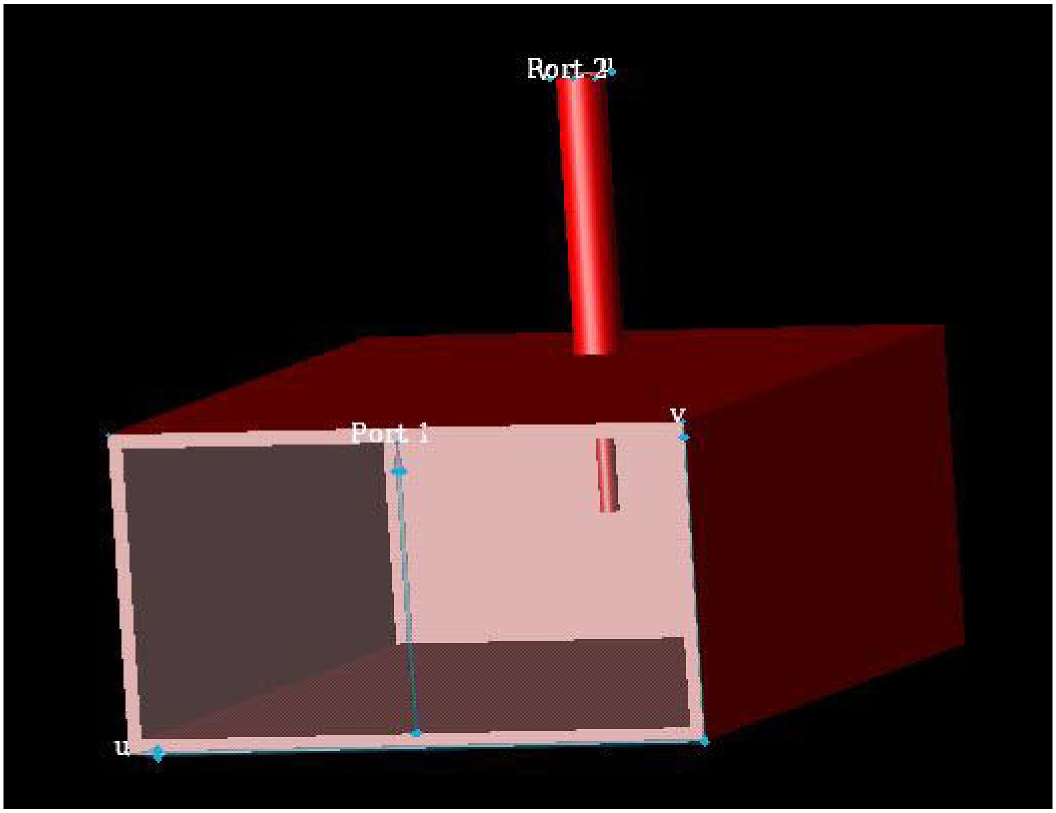


Waveguide to Coaxial Transition

Location: In EMPro, choose **Help** > **Examples** > **Waveguide to Coax**.

Objective

This example describes the design of waveguide to coaxial line transition with waveguide ports using FEM engine of EMPro. The following figure displays a Waveguide to Coaxial line transition:



Setup

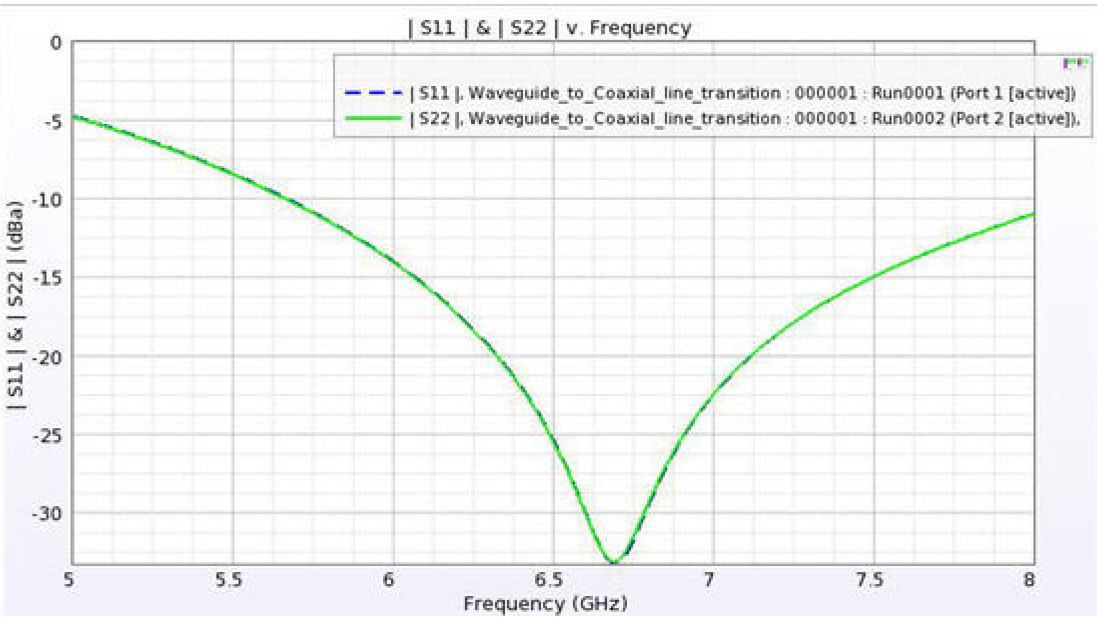
The waveguide used in transition design is WR159. The coaxial section is of 50 Ohm with air dielectric. The design band is C band and probe depth in waveguide section and short plane location is used to get return loss(S11 & S22) better than -10dB between 5 Ghz and 8 GHz.

Archive files: **Waveguide_to_Coaxial_line_transition.zep**

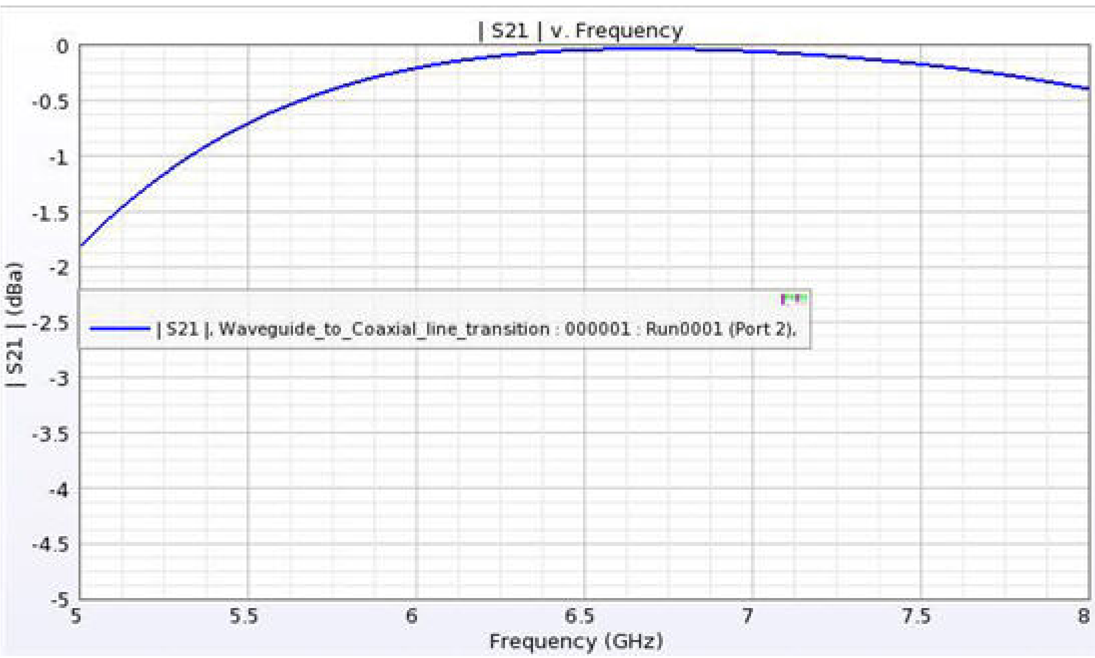
Analysis

The waveguide to coaxial line transition is analyzed for dominant mode(TE01) propagation in waveguide section and TEM mode coaxial section. The S parameter plot over the frequency band is shown in the following figures:

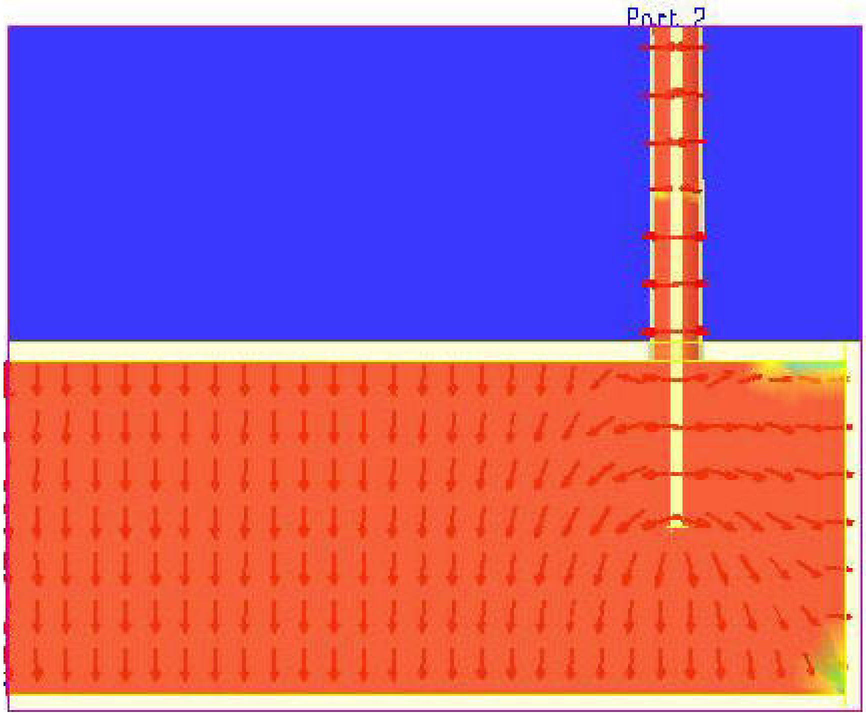
S11 & S22 Parameter Plot



S21 Parameter Plot



The field plot can be seen from Advanced visualization. Field plot for one cut plane that shows the coupling from waveguide to coaxial section is displayed in the following figure:



Note:
Simulate the project **Waveguide_to_Coaxial_line_transition.ep** to see the field plots in Advanced visualization results.

Planar RF Component

This section provides information about the following topics:

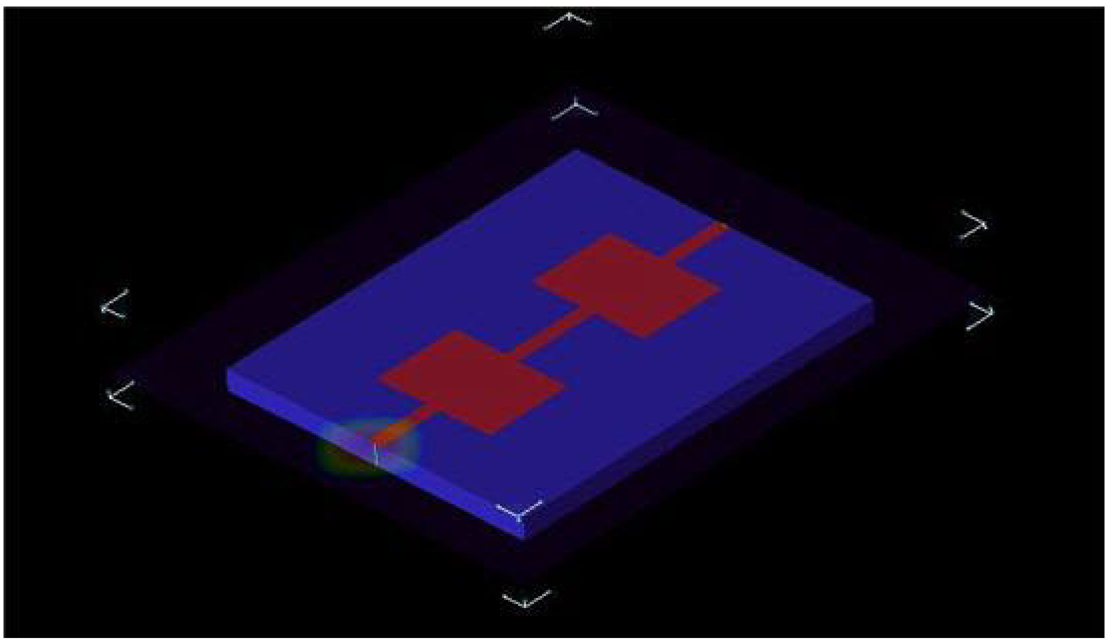
- *Low Pass Filter* (example)
- *LTCC Balun* (example)
- *Microstrip Line* (example)

Low Pass Filter

Location: In EMPro, choose **Help > Examples > Low Pass Filter** to open the project.

Objective

This example illustrates the application of EMPro for the design of planar microstrip passive components such as filter using FEM and FDTD simulations. A stepped impedance low pass filter is displayed in the following figure. In this figure, low pass filter is designed on a substrate of dielectric constant 3 having thickness of 0.64 mm. EMPro provides various types of Near Field sensors through which several field quantities like E, H, B, poynting vector S and surface currents on the surface of the component can be evaluated. In this example, the Surface sensor that is located at port 1 is used to evaluate E, H, and B field quantities along with Surface current Jc and poynting vector S.



Setup

FDTD Setup

A Broadband pulse is used as the source waveform to provide a wide bandwidth frequency response from a single simulation. The 0.3 mm base cell size is used. Adaptive mesh is used along the thickness of the Substrate. The waveform and mesh setup can provide results up to the 100 GHz frequency. The useful frequency range for this device is 0 to 8 GHz.

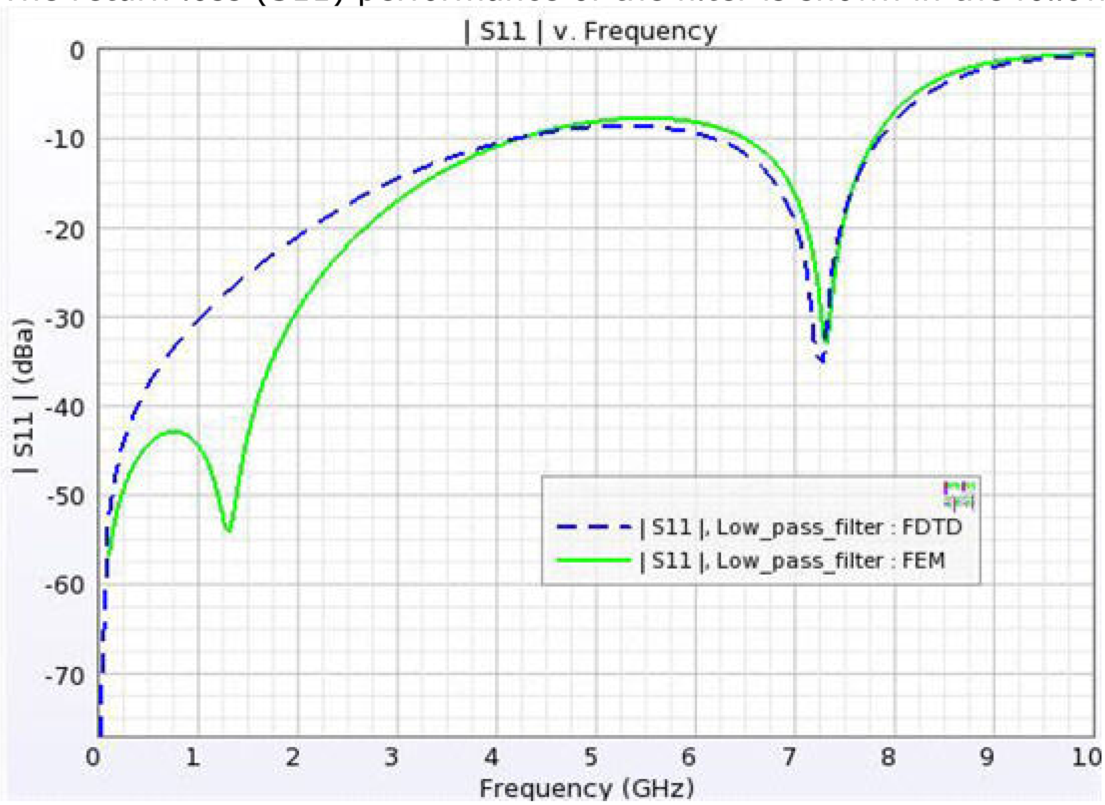
FEM Setup

For FEM simulation same geometry, port and boundary setup as of FDTD is used. FEM padding of 30 mm is used in all the directions except Z. For Z on lower padding is 0 mm on lower side and 20 mm on upper side.

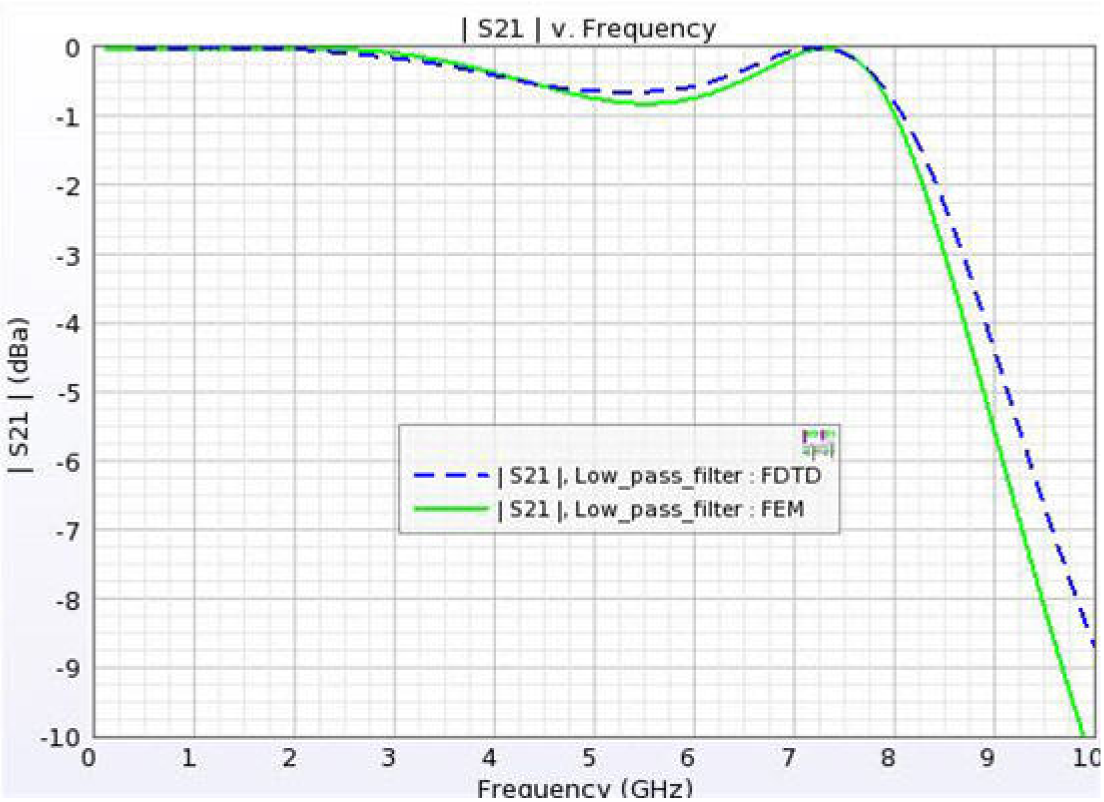
Use the following archive file:
Archive file: **Low_pass_filter.zep**

Analysis

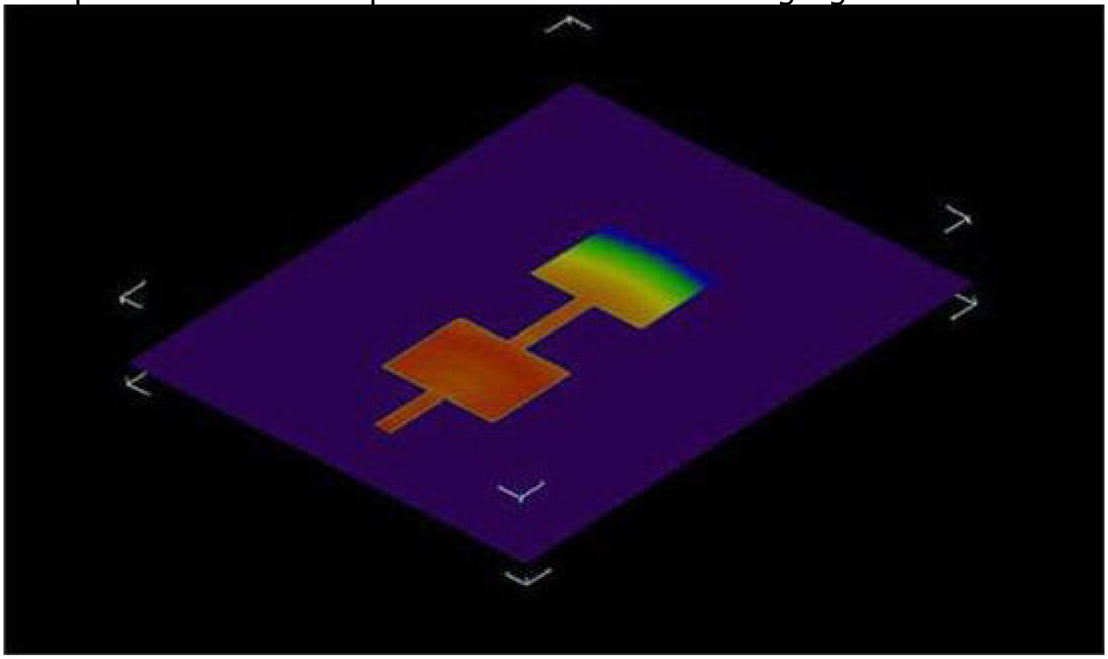
The return loss (S11) performance of the filter is shown in the following figures:



S21 parameter Response



Using the Surface Sensor, different fields E, H, and B poynting vector S and surface current Jc are defined. The progress of these fields with respect to time stepping can be seen in results by choosing Surface Sensor in the output objects. The surface current Jc at one particular time step is shown in the following figure:



In this figure, the field reader tool of EMPro can be used to read the values of quantity which is being plotted over the surface of the low pass filter.

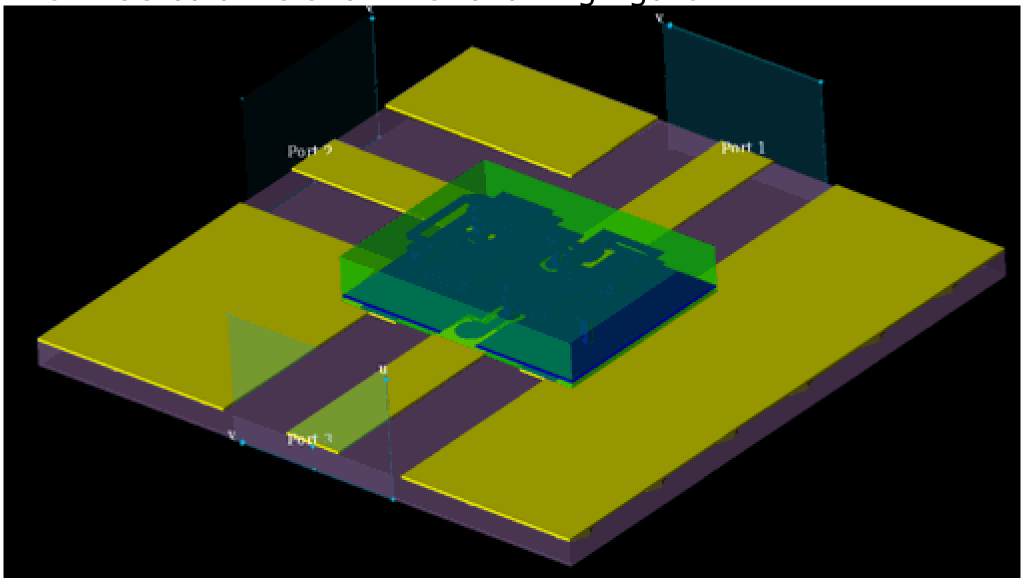
Note
Simulate the project to view the results. For more information about how to create a low pass filter design, refer to *Low Pass Filter* (fdtd).

LTCC Balun

Location: In EMPro, choose **Help > Examples > LTCC Balun** to open the project.

Objective

This example illustrates the design of LTCC Balun using FEM simulator of EMPro. LTCC Balun is designed using finite size dielectric brick. The complete 3D EM analysis takes into account the effect of parasitic close to substrate edges.
The LTCC balun is shown is following figure:



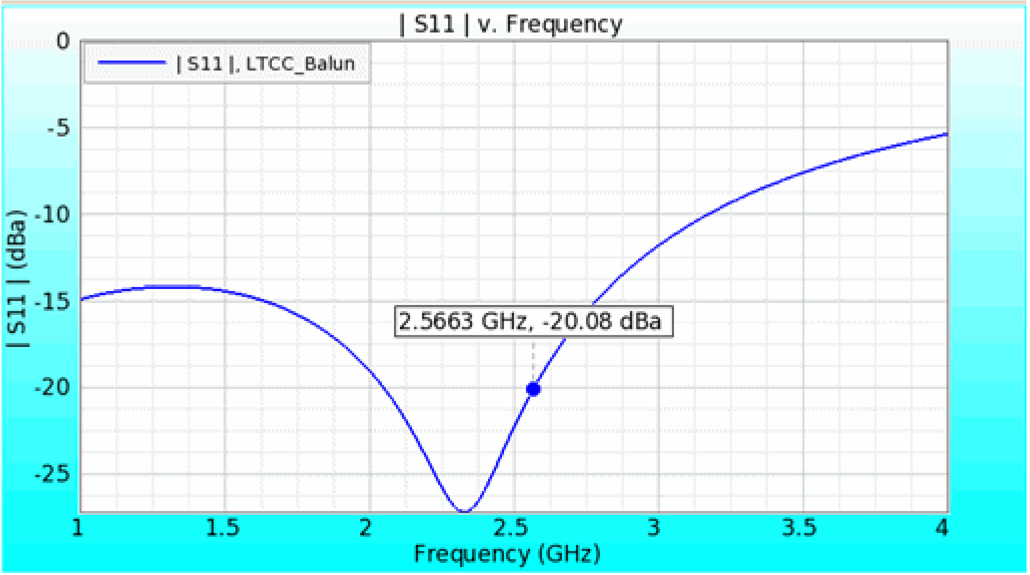
Setup

Absorbing boundary condition is used in all directions except lower Z. Lower Z uses PEC boundary condition. FEM padding of 2 mm is used in upper Z direction. Waveguide port is used with 50 Ohm voltage source.

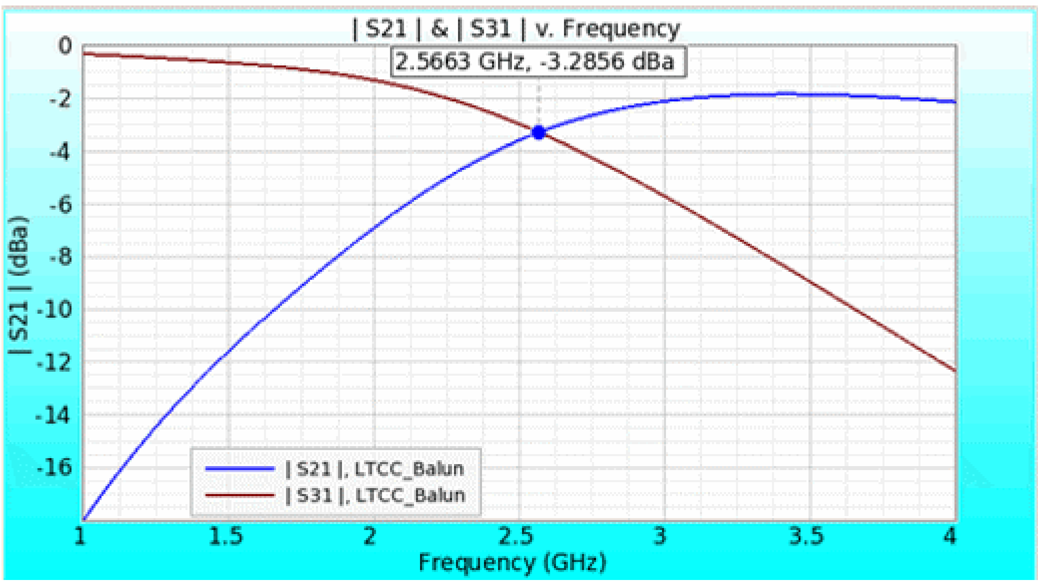
Use the following archive files:
Archive files: **LTCC_Balun.zep**

Analysis

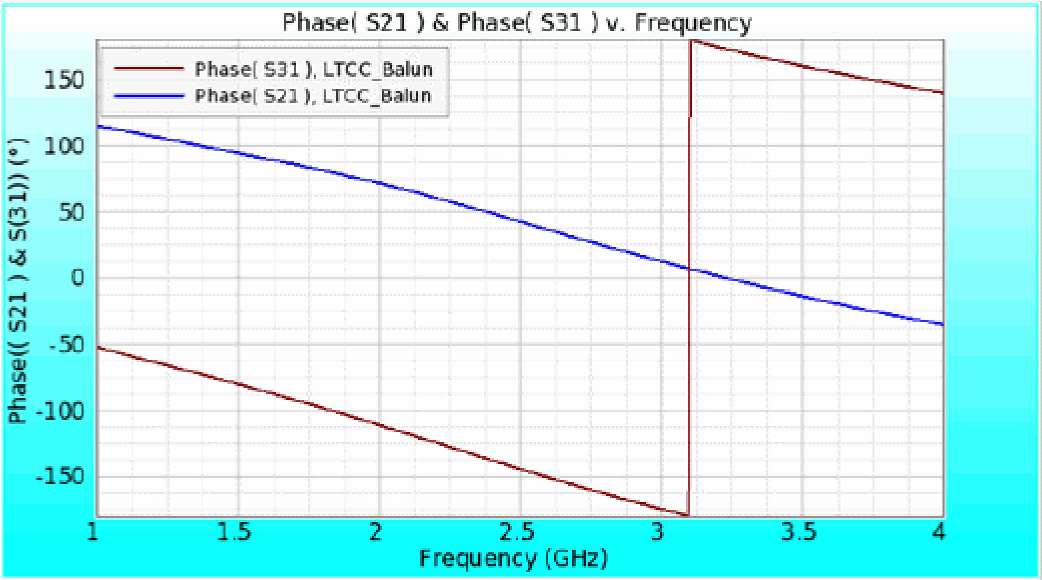
The frequency sweep is carried from 1 GHz to 4 GHz with mesh refinement carried at highest frequency of frequency range.
The S11 plot over the frequency range is shown below:



The S21 and S31 plot is shown below:



The following figure shows the phase of S21 and S31 to see phase balance performance:



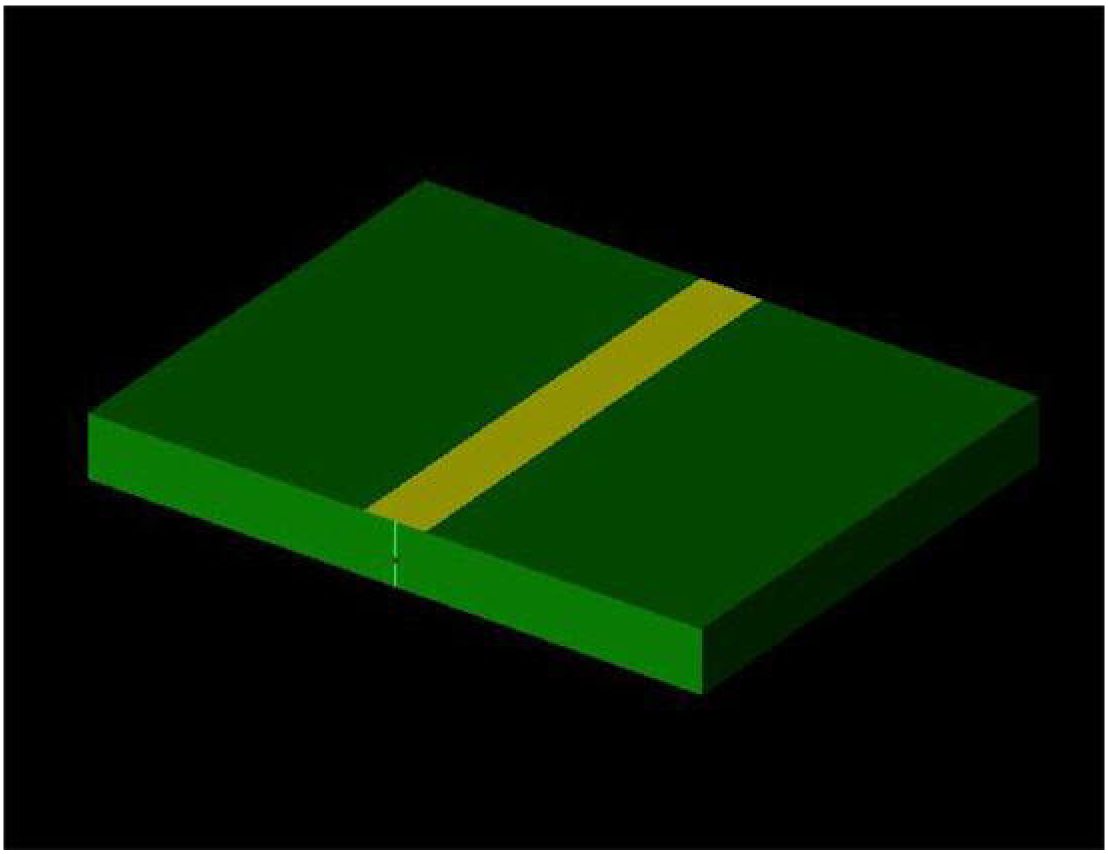
Note
In the **Setup FEM Simulation** window, No field Data option is specified. Therefore, the field data is not available. If field data is required re-simulate the project using reuse option in FEM simulation.

Microstrip Line

Location: In EMPro, choose **Help > Examples > Microstrip Line 50 ohm** to open the project.

Objective

This example describes the design of a Microstrip Line using EMPro using both FEM and FDTD simulations. The line is designed using substrate of dielectric constant 9.9. The thickness of the substrate is 2mm. The width of 50ohm line is 2mm. The Microstrip Line is shown in the following figure:



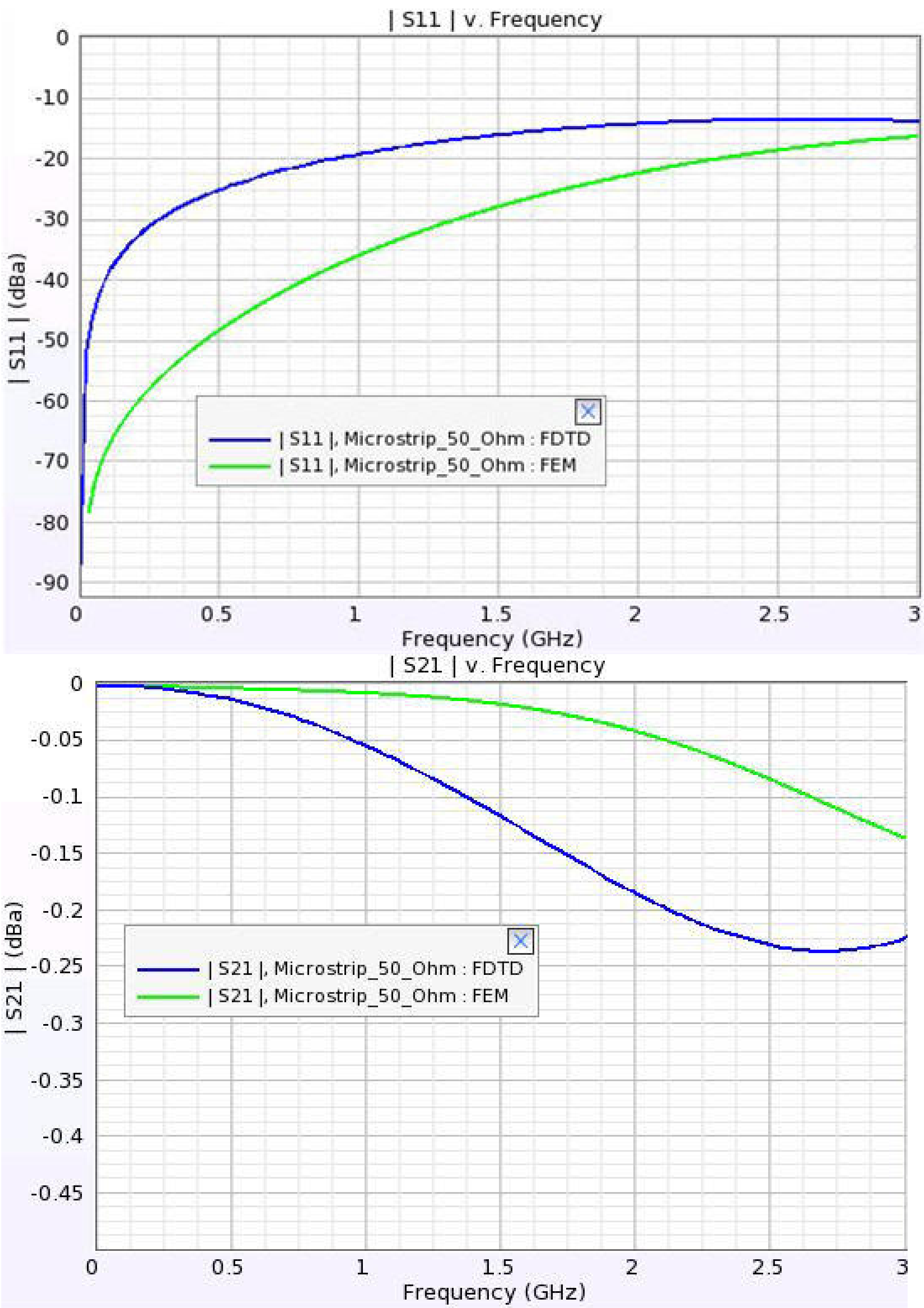
Setup

FDTD:
The broadband pulse is used to excite the two port microstrip line. The base cell size of 1 mm is used in X and Y directions and 0.5 mm is used in Z directions. In addition, for all the objects of the geometry, automatic fixed points is used in gridding properties. Both 2 port simulation is carried out.
FEM:
For FEM simulation same geometry, port and boundary setup as of FDTD is used. FEM padding of 20 mm is used in all the directions except lower Z. For lower Z 0 mm padding is used
Use the following archive files:
Archive files: **Microstrip_50_Ohm.zep**

Analysis

The return loss S11 and S21 performance of the line is shown in the following figure:

S11 and S21 Performance of Microstrip Line



Signal Integrity

This section provides information about the following topics:

- *SATA Connector* (example)
- *Differential Vias* (example)

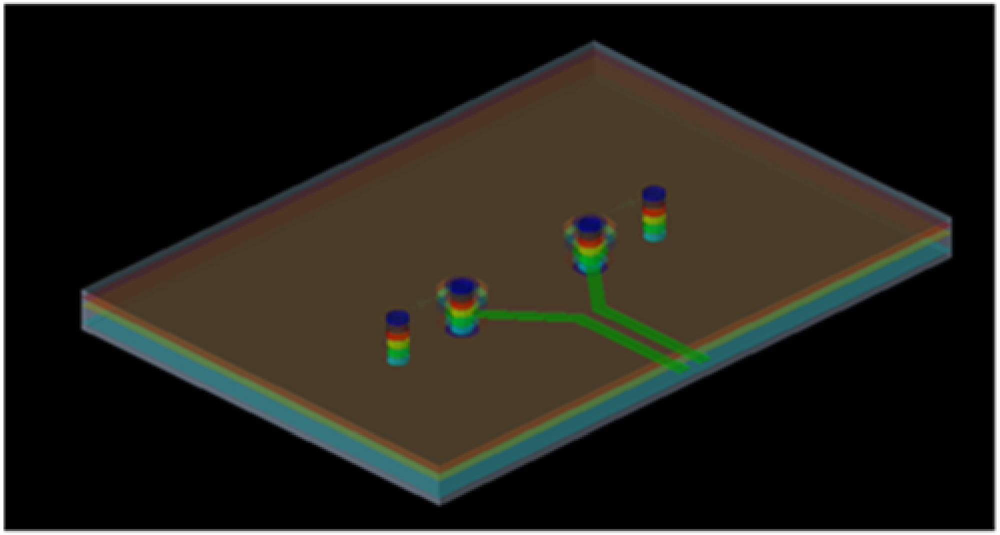
Differential Vias

Location: In EMPro, choose **Help > Examples > Differential Vias** to open the project.

Objective

This examples illustrates the design of Differential Via using FEM simulator of EMPro. Differential Via model is scalable in multilayer structure.

The Differential Via model is shown is following figure:



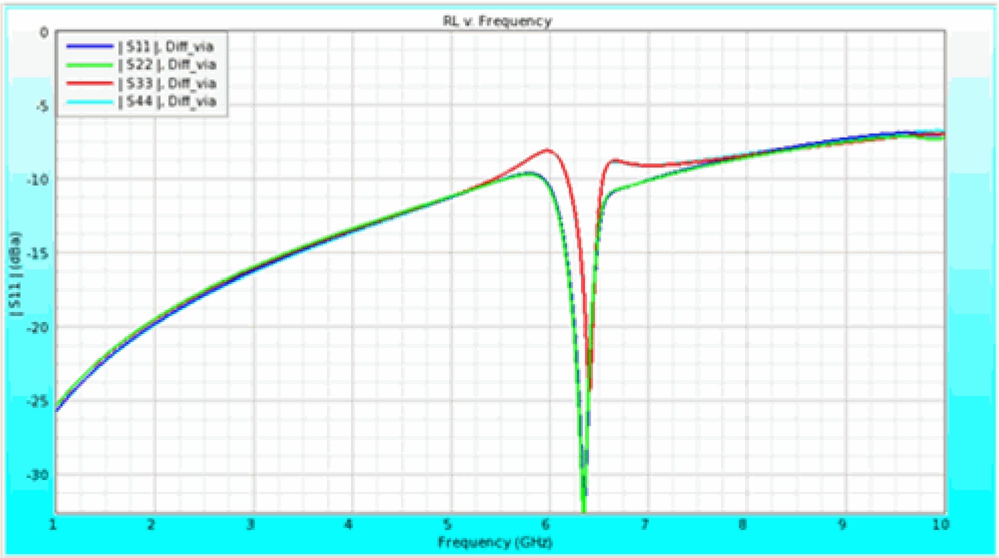
Setup

Absorbing boundary condition is used in all directions. FEM padding of 25 mil is used in upper X and Y direction and 50 mil is used in Z direction.
Use the following archive files:
Archive files: **Diff_via.zep**

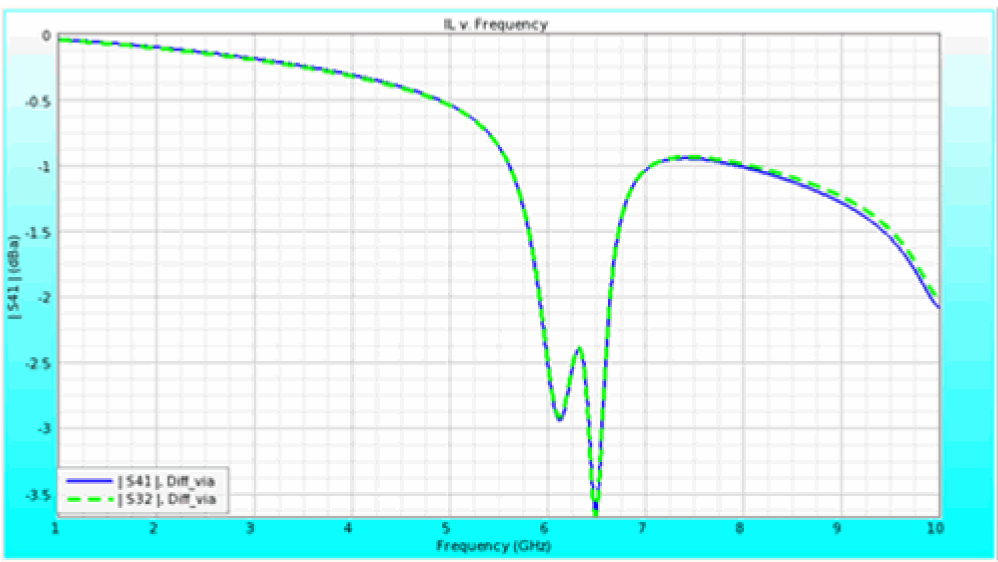
Analysis

The frequency sweep is carried from 1 GHz to 10 GHz with mesh refinement carried at highest frequency of frequency range.

The return loss plot over the frequency range is displayed in the following figure:



The Insertion Loss plot is displayed in the following figure:



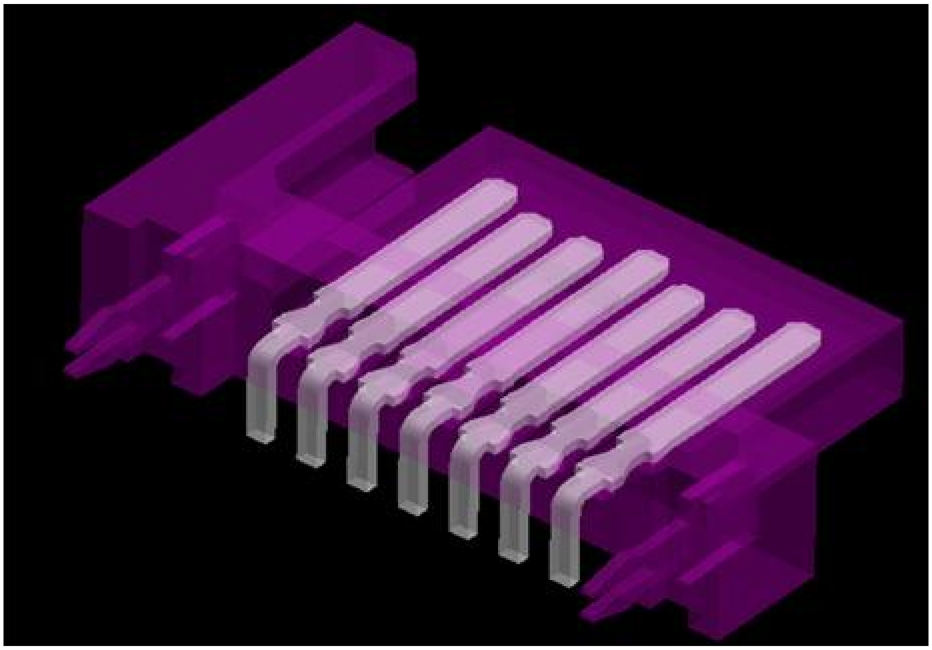
Note
In the **Setup FEM Simulation window, access the *Frequency Plan** tab and choose **User defined frequency** in Field Storage. The field data is available at 1,5 and 10 GHz. If field data is required at any other frequency, again simulate the project by using reuse option in FEM simulation.

SATA Connector

Location: In EMPro, choose **Help > Examples > SATA Connector** to open the project.

Objective

This illustrates the application of EMPro for the simulation of high speed SATA connector. Serial ATA (SATA) interconnect is replacing Parallel ATA (PATA) interface for faster data rate, smaller form factor, and probably lower cost design. Due to the faster data transfer rate, a successful interconnect design such as SATA to PCB interface is crucial to the successful design wins. At Gigabits speed, the high speed interconnects must be characterized by S parameters. The demand for high-speed and high-density interconnects in digital interface designs for PCs, peripherals, and portable devices is rapidly increasing ever than before. Therefore, maintaining the signal quality throughout high-density and high-speed interconnects is crucial due to ever increasing demands for cleaner signal transmission. Nowadays, early design changes based on accurate simulations are indispensable and worthy investments for connector design houses. Therefore, an accurate EM model is highly desirable during the design and implementation stage of high-speed connectors.



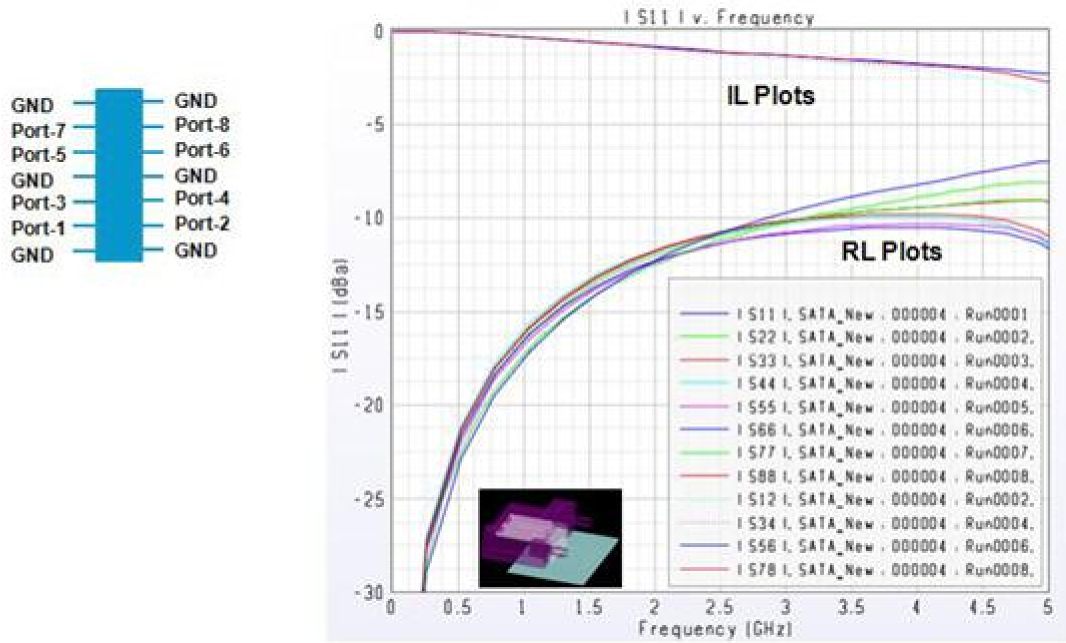
Setup

A SATA signal connector is analyzed with EMPro. SATA connector is simulated with both FDTD and FEM solvers. The EMPro simulation file can be exported as a design kit in ADS so that the connector data can be used for signal integrity analysis along with other board traces in ADS. The SATA connector consists of four conductors in two differential pairs. The 7 pins and 3 pins are ground pins, while 4 pins are used for signal pins. Two pins are for transmitting and the other two for receiving, but both are differential pairs. The housing material for the connector is LCP(Liquid Crystalline Polymer) that has 2.9 dielectric constant.
Archive file: **SATA_connector.zep**

Analysis

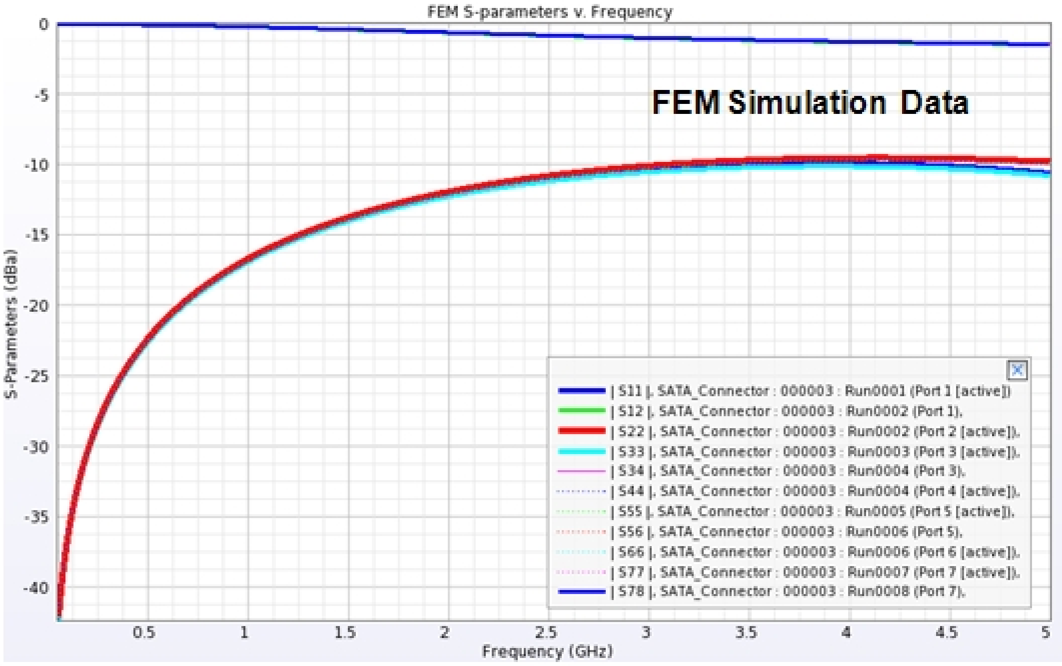
The S parameter performance of SATA Connector is shown in the following figure. Return loss is better than -10 dB up to 2 GHz. Ports 1, 3, 5, and 7 are input ports while ports 2, 4, 6, and 8 are output ports.

S Parameter Performance for FDTD Simulation Result

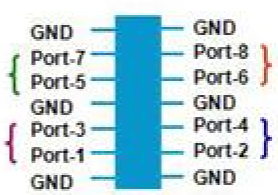


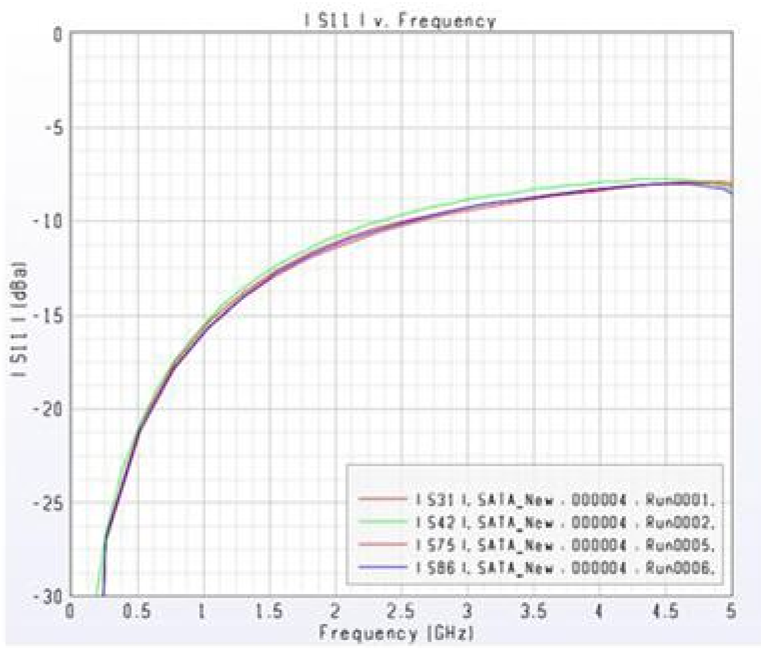
The following figure shows the EMPro simulated data of isolation between adjacent ports (Port 1 and 3, Port 2 and 4, Port 5 and 6 , Port 6 and 8). Port isolations are better than -12dB upto 2GHz.

FEM Simulation Result



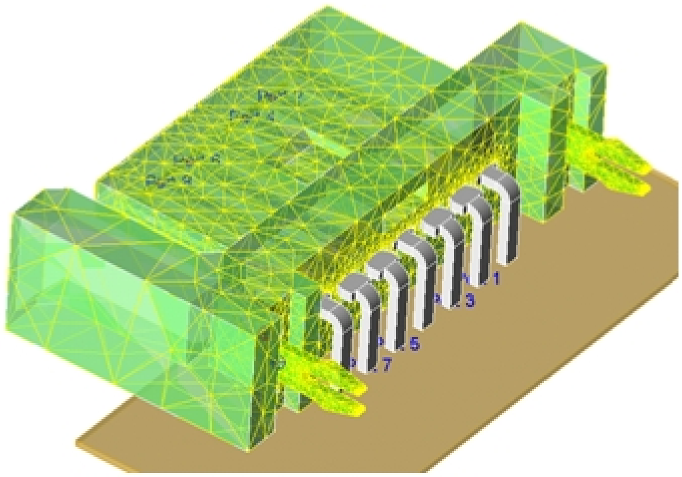
EMPro Simulated Data



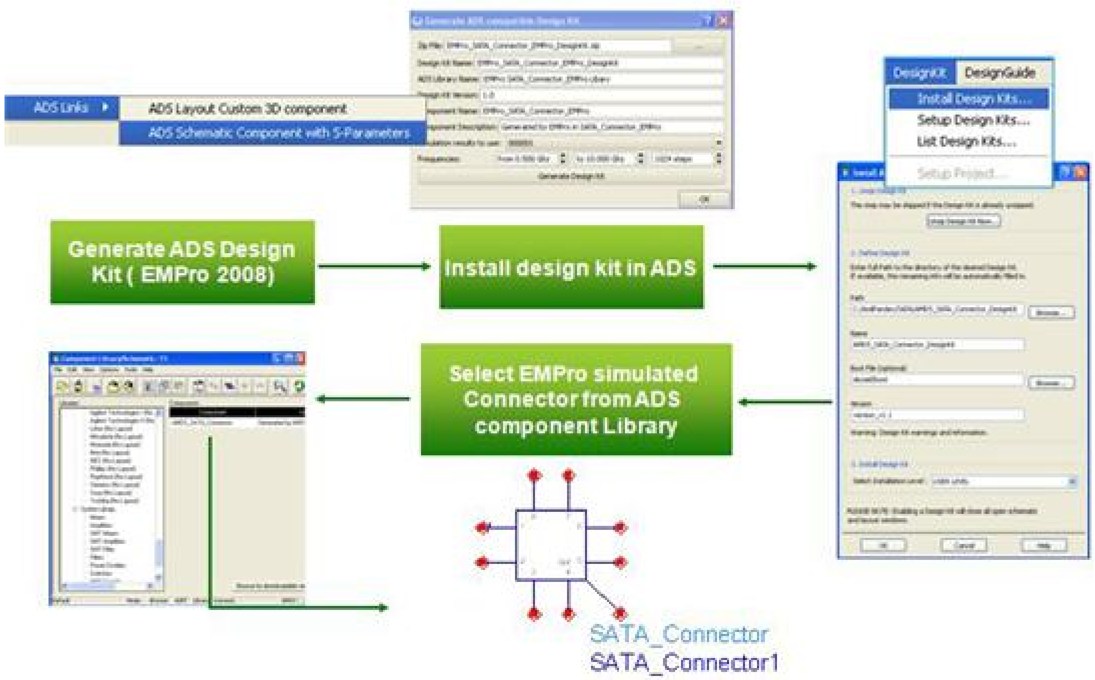


EMPro users can export EMPro designs along with simulated data in a form of design kit to ADS. The S parameters of the connector model were exported as ADS design kit and used in ADS circuit simulators for further SI analysis. This design kit can be installed in ADS and EMPro project can be placed in schematic as a component. Here, the SATA connector simulation model (along with small portion of board trace) is imported in ADS to perform signal integrity on board traces along with connector effect.

Meshing on SATA connector



Flow Diagram



> **Note:**
> To generate the results for all the ports, simulate the project again by making all the ports active.

Eigenmode Solver

This section provides information about the following topics:

- *Eigenmode Solver on a DC-SIR Cylinder* (example)

Eigenmode Solver on a DC-SIR Cylinder

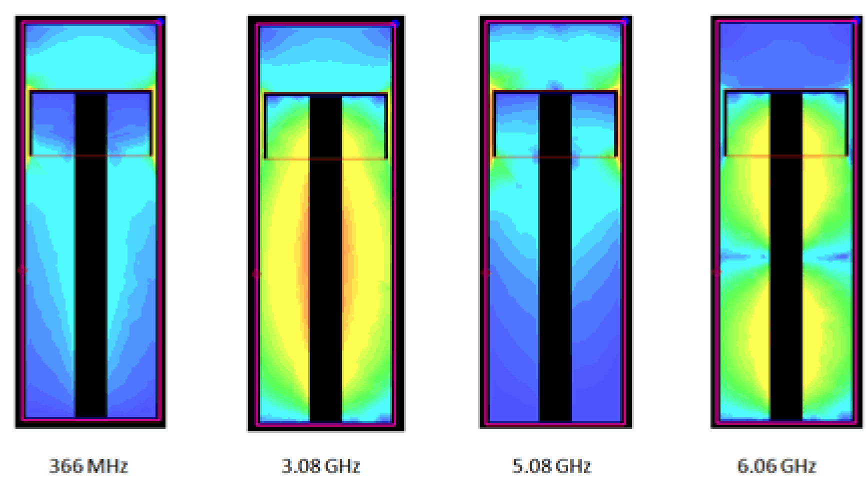
Location: In EMPro, choose **Help** > **Examples** > **Eigenmode Solver on a DC-SIR Cylinder** to open the project.

Objective

In this example, a double coaxial stepped impedance resonator (DC-SIR) is simulated. Currently, EMPro does not support cylindrical boundaries. For cylindrical or other non-rectangle cavities, it is important to put a rectangular metal background to avoid external artificial cavities between the metal walls and FEM boundaries.

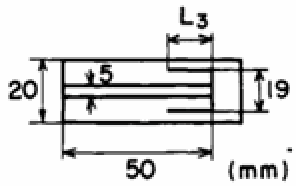
Setup

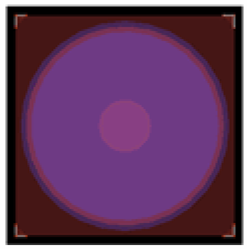
The dimension of the resonator is shown in the following figure, where L3 is set to be 10 mm in this simulation:



Analysis

The Eigen frequencies and Q values are shown below with copper metals. The total elapsed time is 46 seconds. Note that the eigenmode solver is multi-threaded so that the *Elapsed time* is shorter than the *CPU time* in each solving pass. The eigen fields at corresponding frequencies are shown in the following figure:





The following figure displays the eigen fields for DC-SIR:

```
INITIAL MESH
------------

nbPoints      : 912
nbTetrahedra  : 3128

REFINING
--------
                    |               MESHING                |                               SOLVING
 level   freq(GHz)  |  nbTetr  Elapsed time    CPU time    |  nbUnknowns    mem(GB)   Elapsed time    CPU time  Delta(S)
--------------------|--------------------------------------|---------------------------------------------------------------------
     1              |    3128    00:00:08.1  00:00:07.8    |       23854      0.226     00:00:09.1  00:00:22.8         /
     2              |    3796    00:00:01.0  00:00:01.0    |       28396      0.270     00:00:11.2  00:00:27.7     0.002[->0.010]
     3              |    4510    00:00:01.3  00:00:01.2    |       33384      0.312     00:00:13.7  00:00:33.6     0.002[->0.010]


     Eigenfrequencies | Q values

    1.  3.664557e+008 | 1.166295e+003
    2.  3.080868e+009 | 3.066764e+003
    3.  5.077350e+009 | 5.705200e+002
    4.  6.056062e+009 | 4.404977e+003



 Total Elapsed Time = 0:00:46
```

General Examples

This section provides information about the following topics:

- *Agilent Phone* (example)
- *QFN Package* (example)
- *RCS of Aircraft* (example)

Agilent Phone

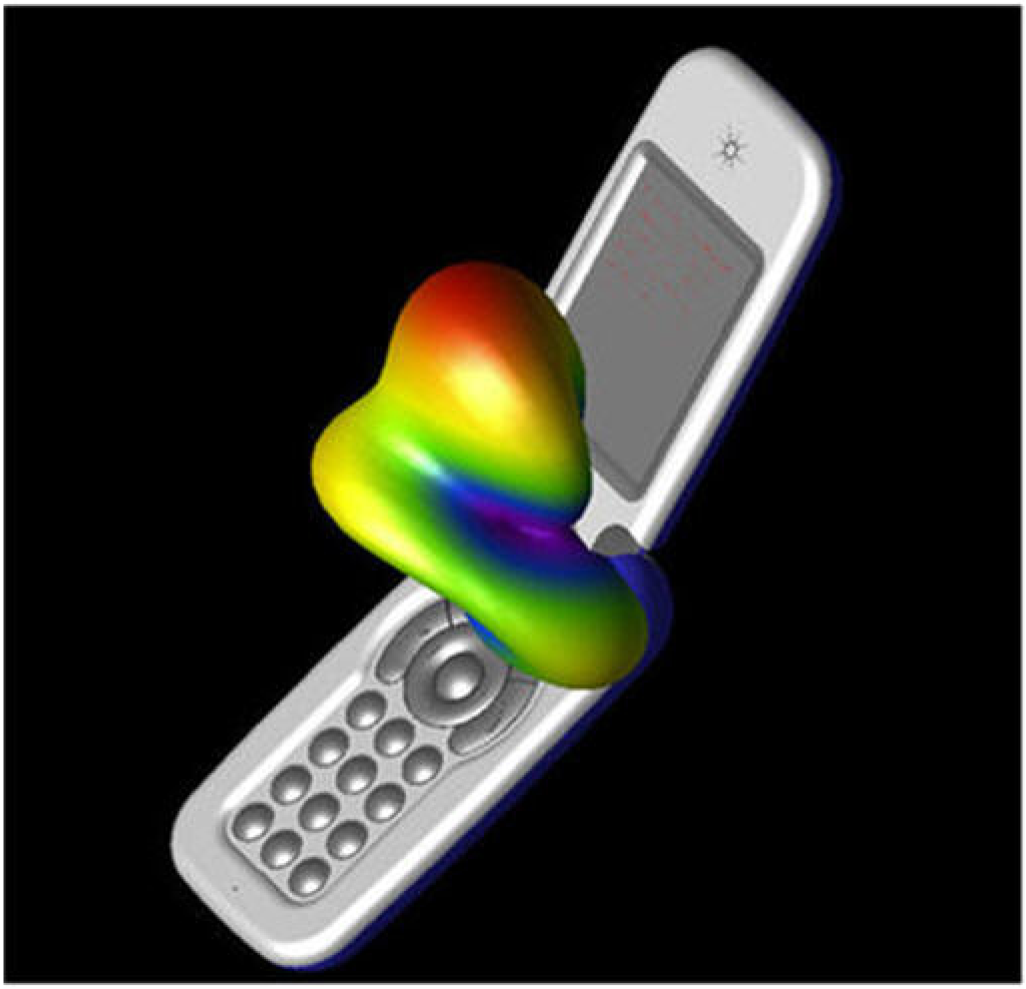
Location: In EMPro, choose **Help > Examples > Agilent Phone** or **Help > Examples > Agilent Phone with Phantom** to open the projects.

Objective

This example illustrates the capability of EMPro in designing Mobile phone antenna system and qualify it for SAR and HAC standards. Antenna used in a mobile phones operates in mobile phone casing with many associated materials of different dielectric constant around it. Therefore, antennas like GSM or Bluetooth should be designed and analyzed in the within mobile phone casing in presence of different types of materials. EMPro has advanced CAD import facility that allows the import of CAD files in almost all the industry used CAD files formats such as sat, sab, iges, dxf, stp, ProE, aunigraphics, and inventor.

In this example, the mobile phone CAD file is imported in the sat format. The project is configured by assigning different materials to different components. In this example, two antennas, one operating at the GSM band and another operating at Bluetooth are analyzed. The mobile phone structure is also analyzed in the presence of a human head structure to calculate the SAR maximum and average data. The Agilent phone is shown in the following figure where both GSM and Bluetooth antennas are placed.

Agilent Phone



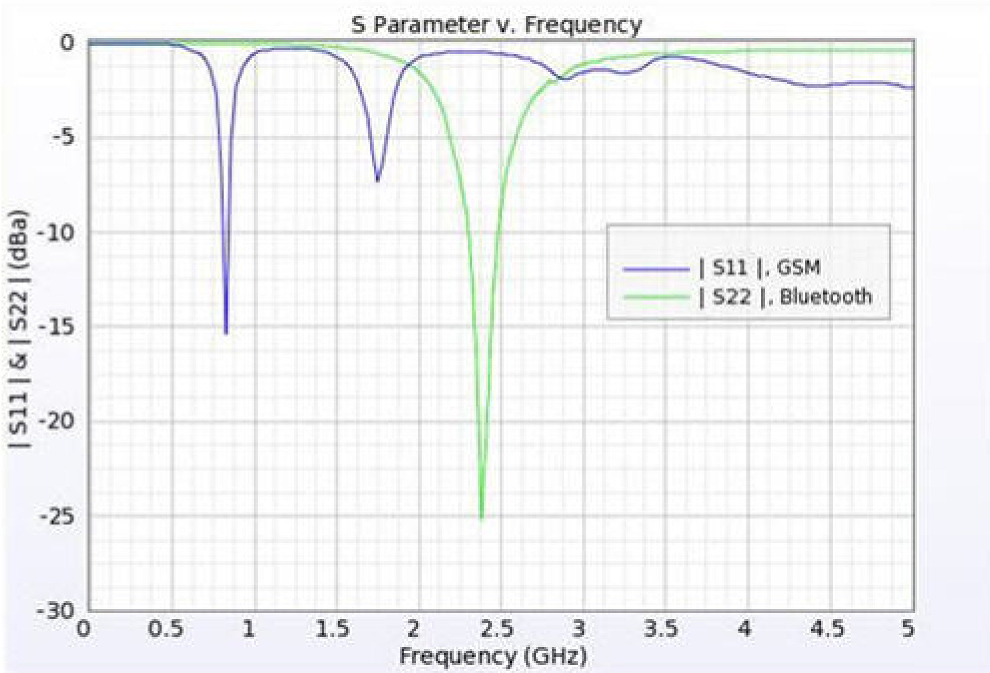
Setup

A CAD file having the mobile phone structure with both antennas is imported in EMPro. The project is set up in EMPro by assigning materials to different components, defining ports for both GSM and Bluetooth antenna and defining mesh. To analyze the performance of antennas in the presence of human head structure, a CAD file human head structure is also imported and material for inner and outer shell is assigned. Use the following archive files:
Archive files: **AGILENT_PHONE.zep, AGILENT_PHONE_HEAD.zep**

Analysis

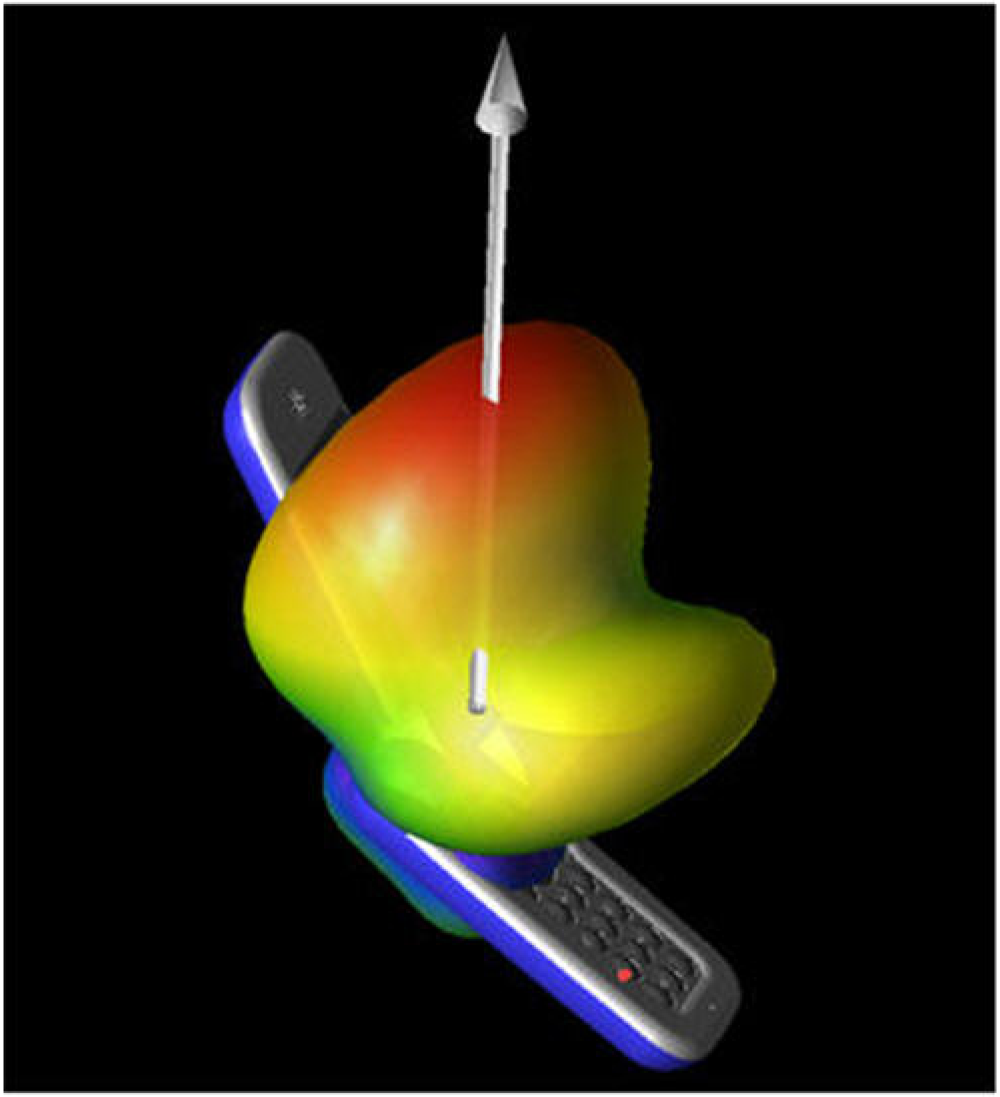
The return loss performance of both GSM and Bluetooth antenna are shown in the following figure.
The GSM antenna has -15dB and -7dB return loss in GSM bands.
The Bluetooth antenna gives -25dB return loss.

Return Loss Perfomance



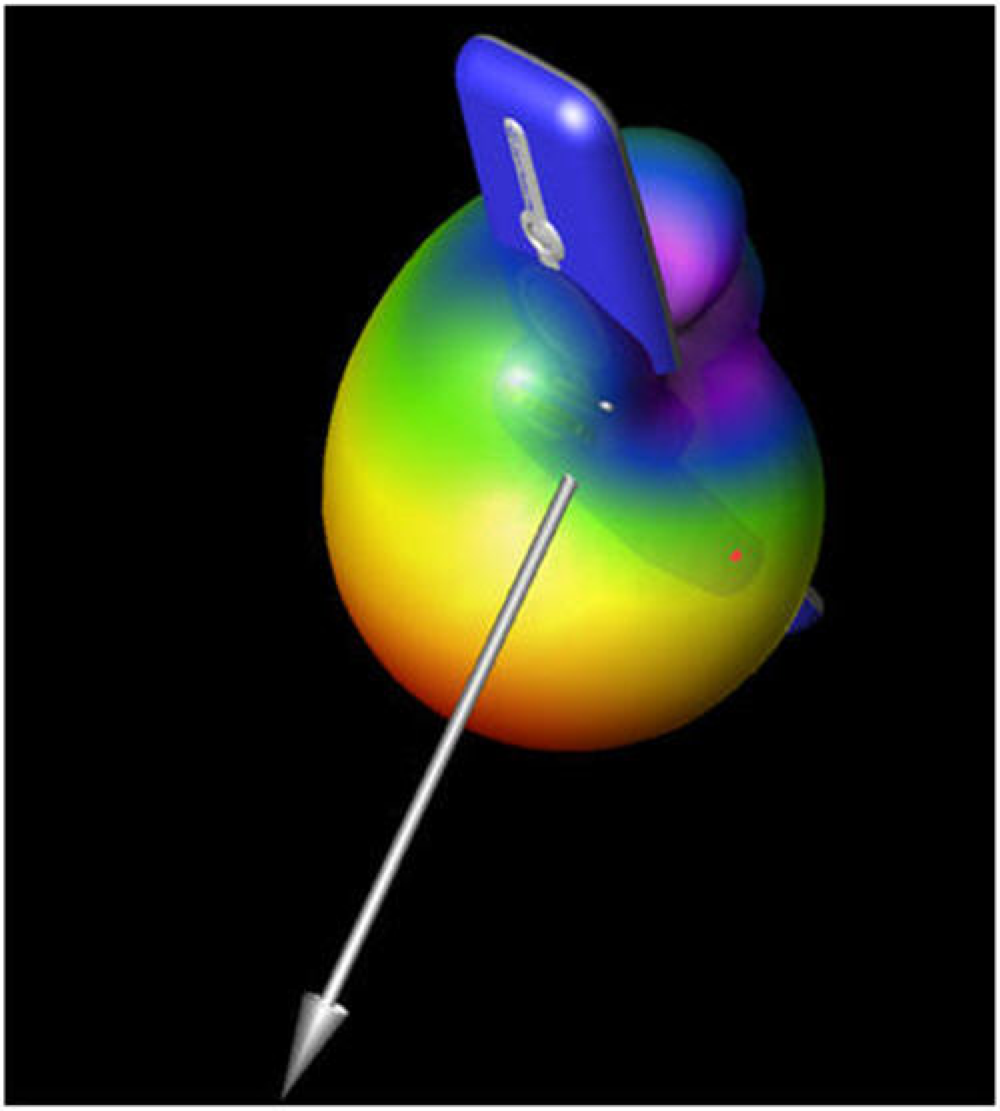
The GSM antenna is located at the bottom of the phone. The radiation pattern of the GSM antenna in presence of complete mobile phone structure is shown in the following figure:

Radiation Pattern for a GSM Antenna



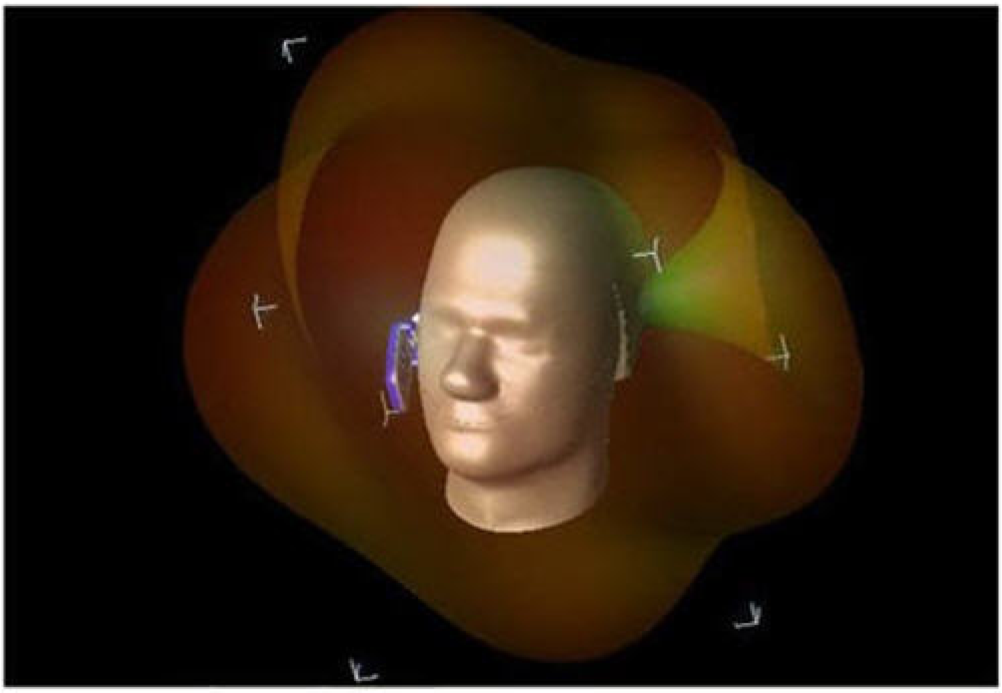
Similarly, the radiation pattern of Bluetooth antenna is shown in the following figure:

Radiation Pattern for a Bluetooth Antenna



The analysis of a GSM antenna for S parameter and radiation pattern along with SAR calculation is done in separate project *AGILENT_PHONE_HEAD.ep*. The pattern of the antenna gets distorted in the presence of a human head structure. The following figure shows the radiation pattern of a GSM antenna in the presence of a human head structure:

Radiation Pattern in the Presence of a Human Head Structure



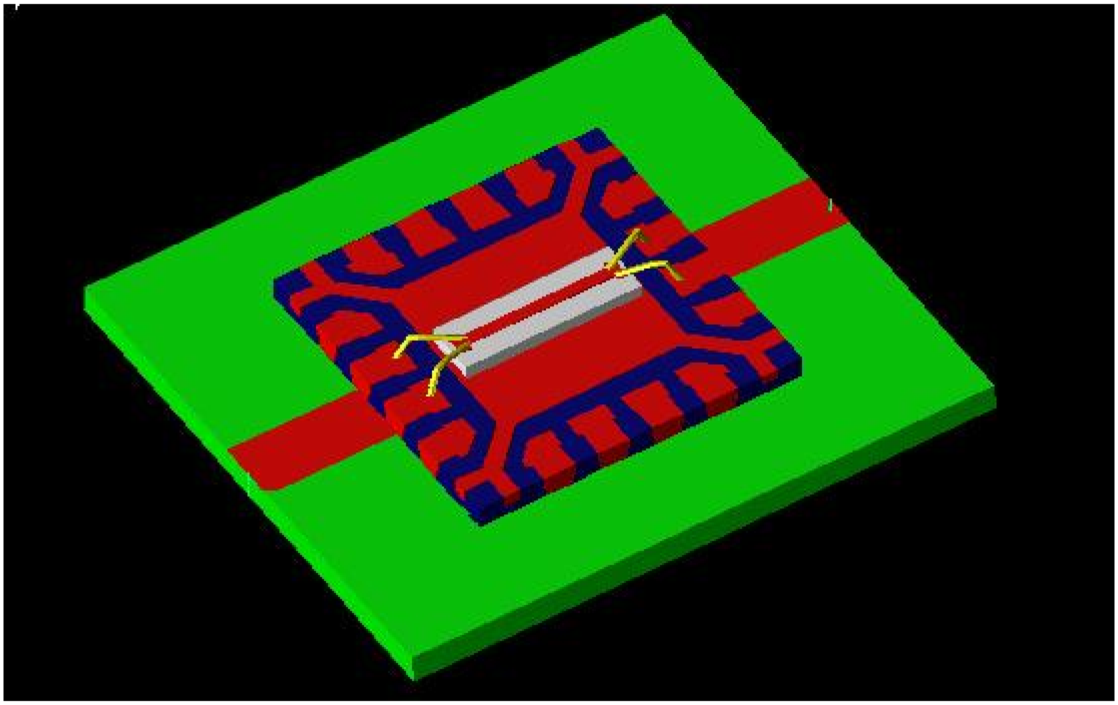
In the project, the result for SAR 10g, 1g, and RAW data is also shown. These results show the SAR maximum value and its location for 1.8 GHz. In addition, the SAR average 1g and 10g at different location of the geometry can also be seen in results.

QFN Package

Location: In EMPro, choose **Help** > **Examples** > **QFN Package**

Overview

This example describes the FEM simulation of a QFN Package. The QFN package model is imported in EMPro from CAD model.



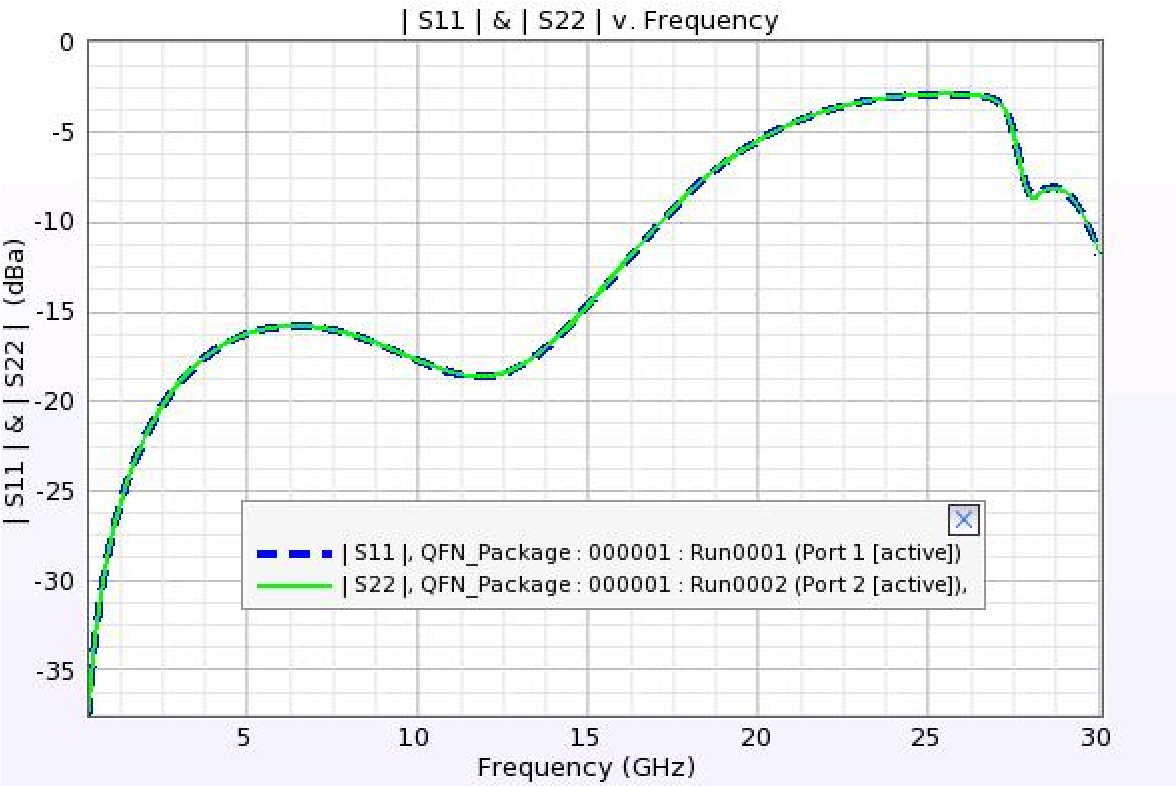
Setup

The FEM simulation is carried out from 0-30 GHz. The boundary condition is absorbing on all the sides except lower Z. In lower Z side the PEC boundary condition is applied. This is a two port structure. Internal ports are used for the simulation
Archive files: **QFN_Package.zep**

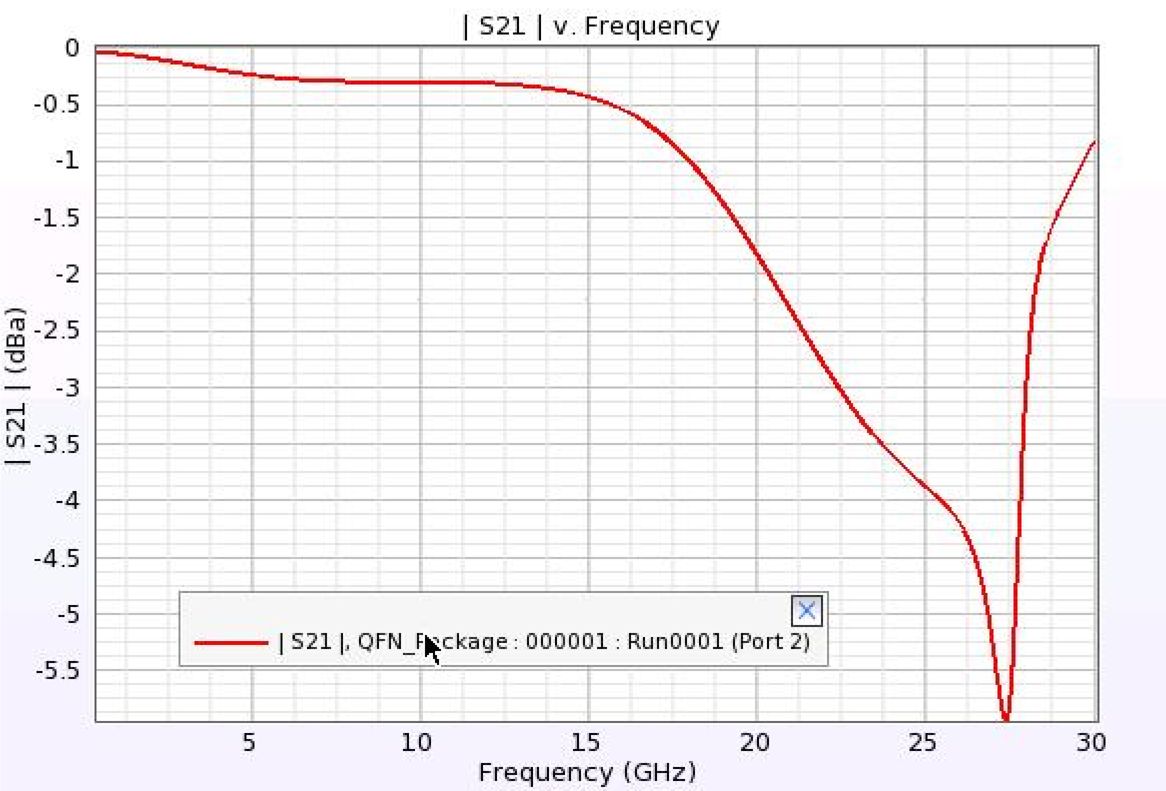
Analysis

The QFN package is analyzed at mesh frequency of 30 GHz, which is the highest frequency of the band. The S parameter plot over the frequency band is shown in the following figure:

S11 & S22 Parameter Plot

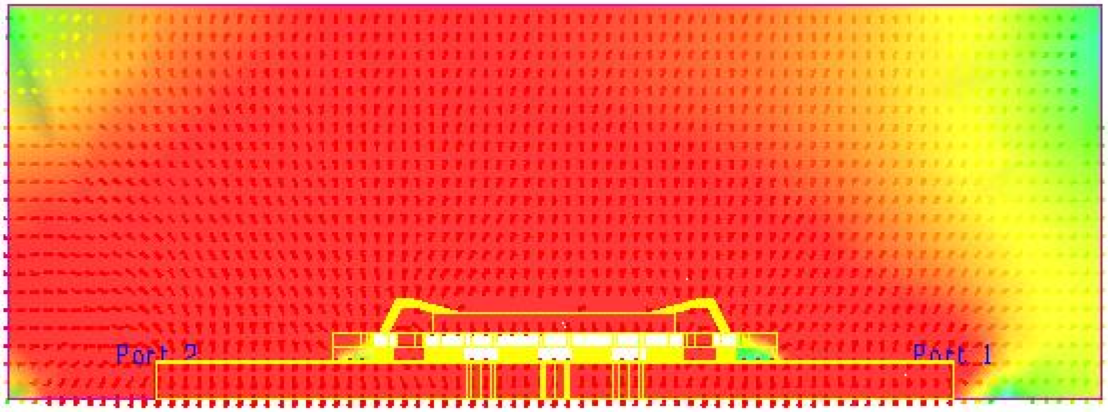


S21 Parameter Plot



Field Plot

The field plot can be seen from Advanced visualization. Field plot for one cut plane in the structure is shown below:



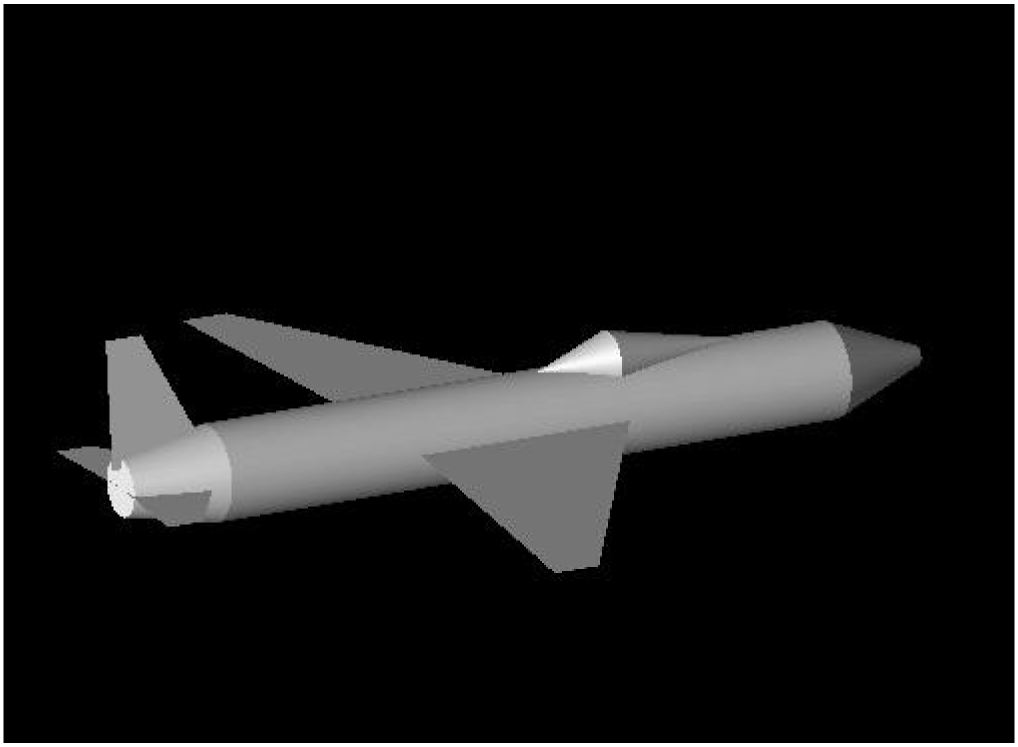
Note:
Simulate the project **Waveguide_power_divider.ep** to see the field plots in Advanced visualization results.

RCS of Aircraft

Location: In EMPro, choose **Help > Examples > Example Projects > RCS of Aircraft** to open the project.

Objective

This example describes the application of EMPro for evaluating the Radar Cross Section (RCS) of an Aircraft. EMPro provides the facility to excite different surfaces and structures by an external source. Both Plane wave and Gaussian beam type of external source are available in EMPro. The external source also provides the facility to excite in either of Ephi or Etheta polarization in any incident phi or theta directions. The aircraft that is used in this example is is 9m in length and is imported in EMPro through robust CAD import facility. EMPro consists of the advanced CAD import facility that supports all standard CAD files formats such as: sat, sab, iges, dxf, stp, ProE, unigraphics, and inventor. The following figure displays the aircraft model:



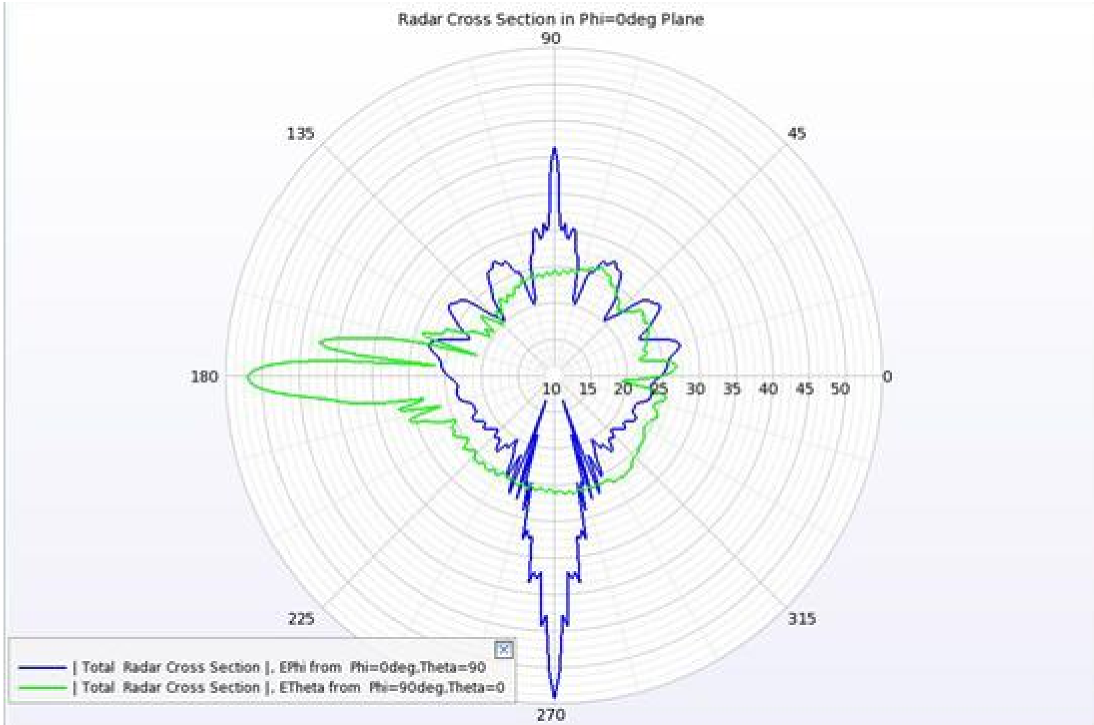
Setup

The RCS is evaluated at 1GHZ. The geometry is 30 lambda in length at this frequency and EMPro is able to calculate RCS of the aircraft. The broadband pulse is used in waveform. The base cell size of 25mm is used with 20 padding in all the directions. The plane wave source is used for external excitation. Two simulations were carried out for different incident directions and polarizations. In the first simulation, E phi Polarization is used from Phi at 0 degrees and Theta at 90 degrees incident direction. In the second simulation, the ETheta polarization is used from Phi at 90 degrees and Theta at 0 degrees incident direction. In both of these simulations, the total/Scattered field formulation is used and without computing the dissipated power. These settings makes easy convergence and fast simulation. Use the following archive files:

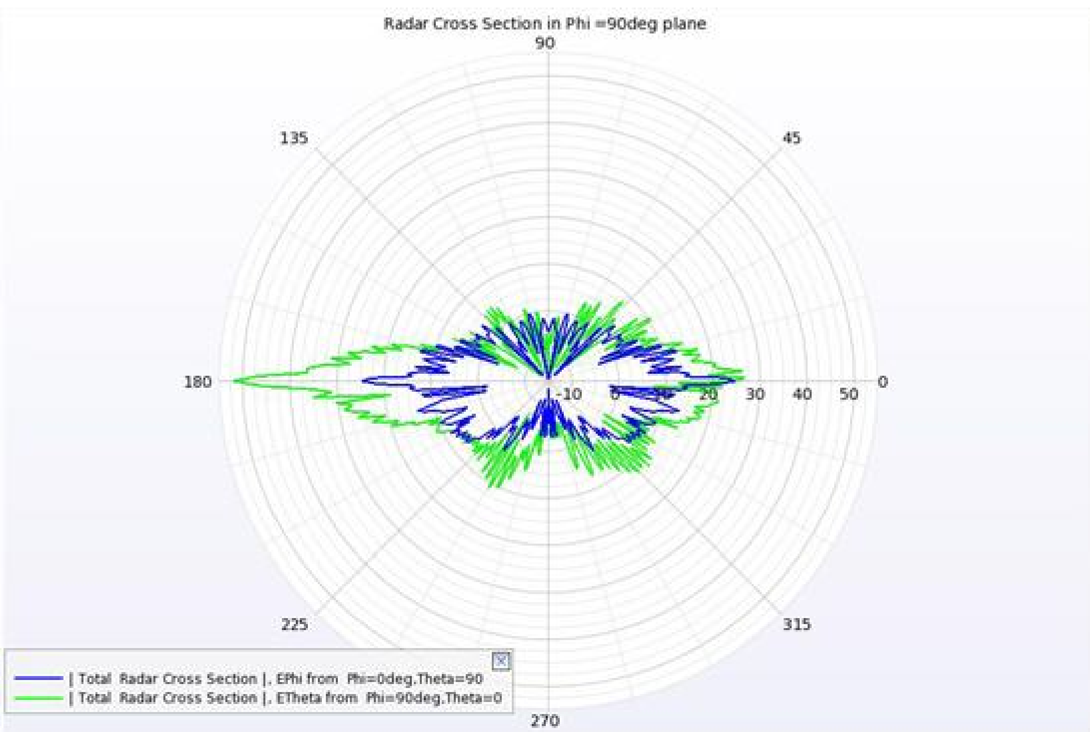
Archive files: **RCS_Aircraft.zep**

Analysis

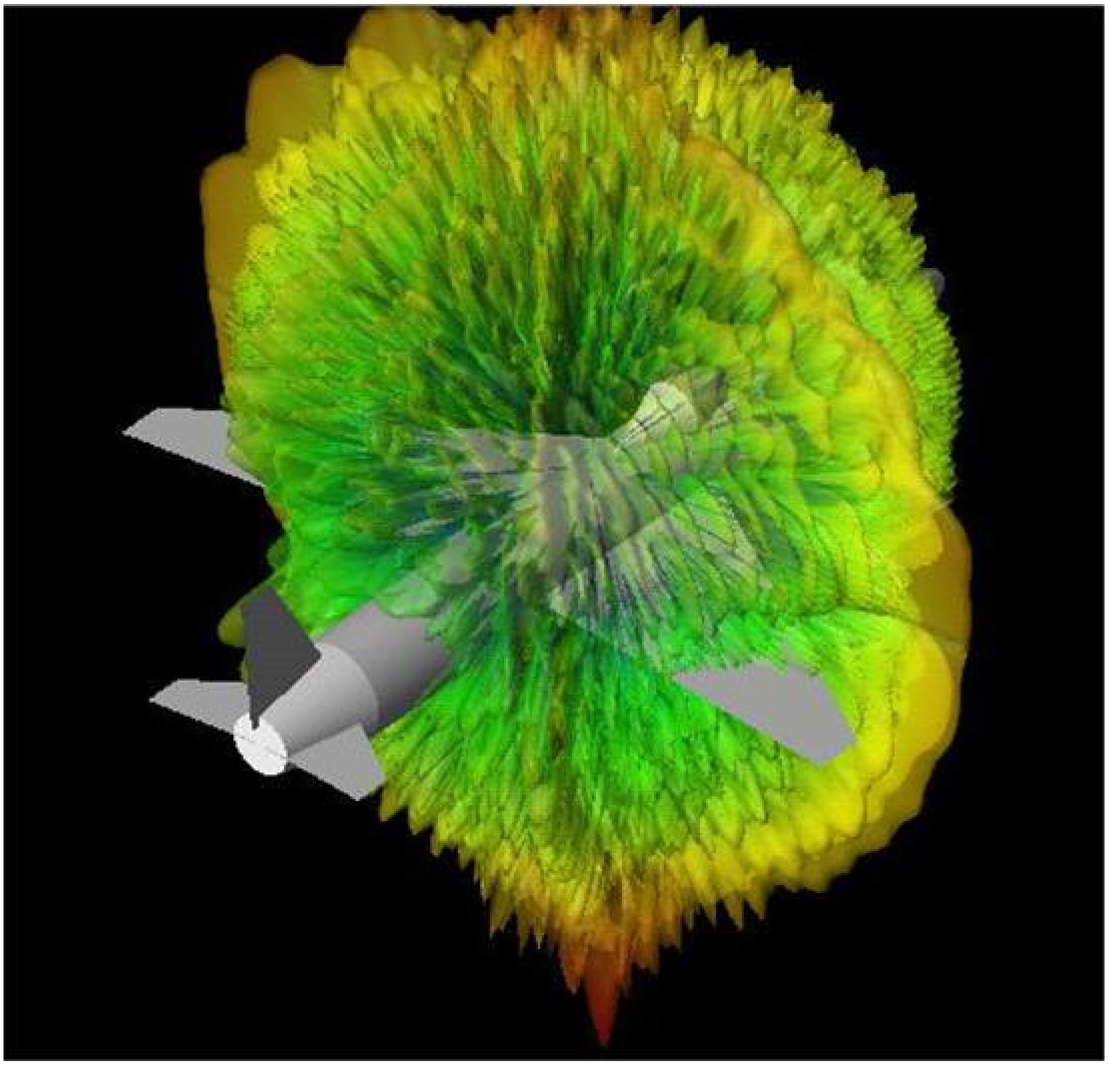
The RCS plot in Phi at 0 degrees plane cut for both simulations is shown in the following figure:



The RCS plot in Phi at 90 degrees plane cut for both the simulation is shown in the following figure:



The 3D RCS plot for simulation 1 is shown in the following figure. The RCS value is 54.32dBsm.



The 3D RCS plot for simulation 2 is shown in the following figure. The RCS value is 51.89dBsm.